

FIG. 1

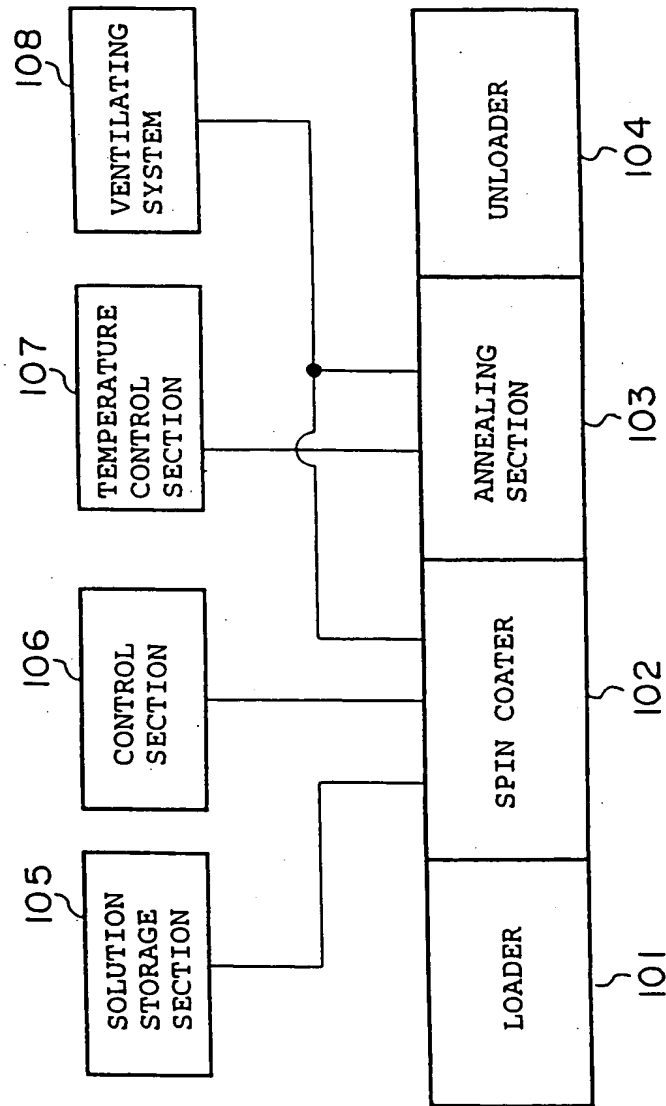


FIG. 2

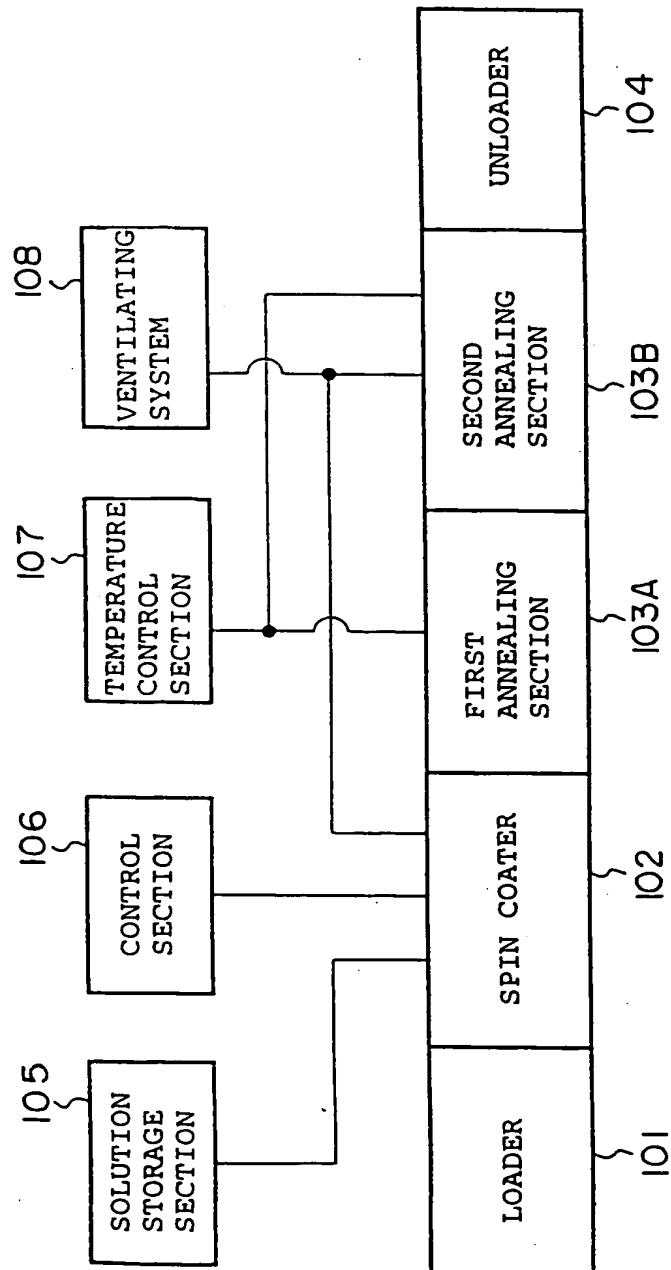
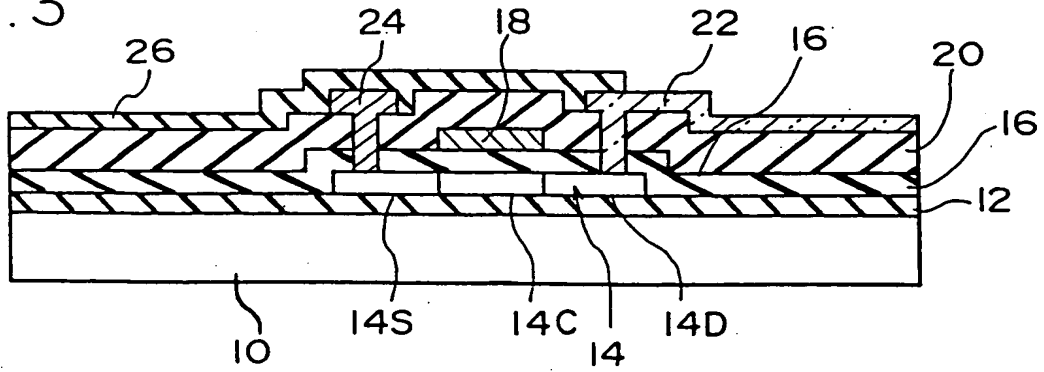
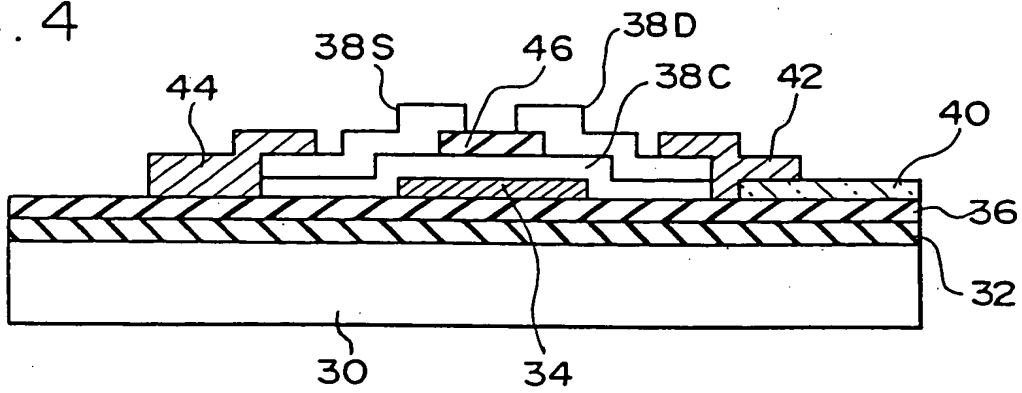


FIG. 3



-- PRIOR ART --

FIG. 4



-- PRIOR ART --

FIG. 5

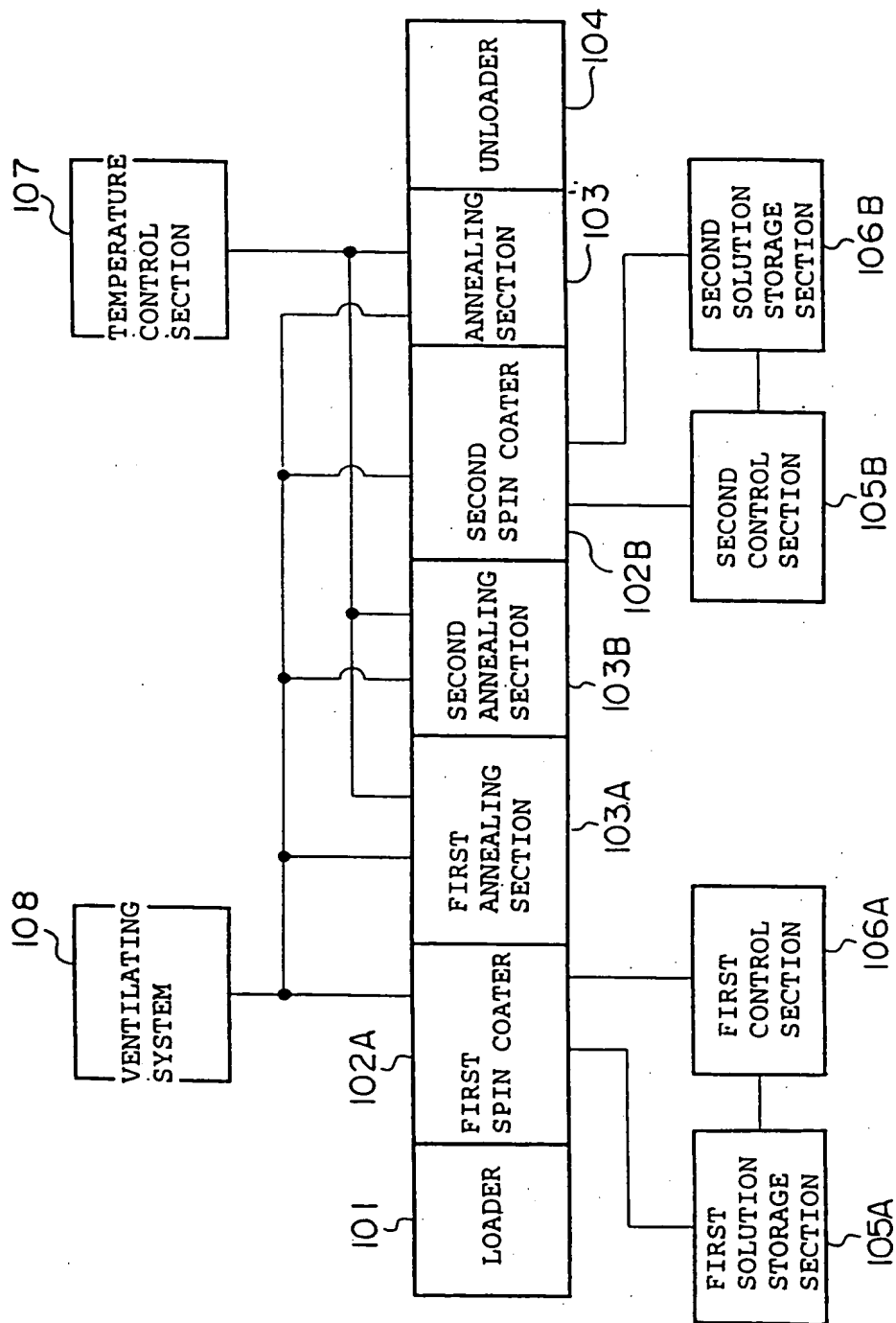


FIG. 6

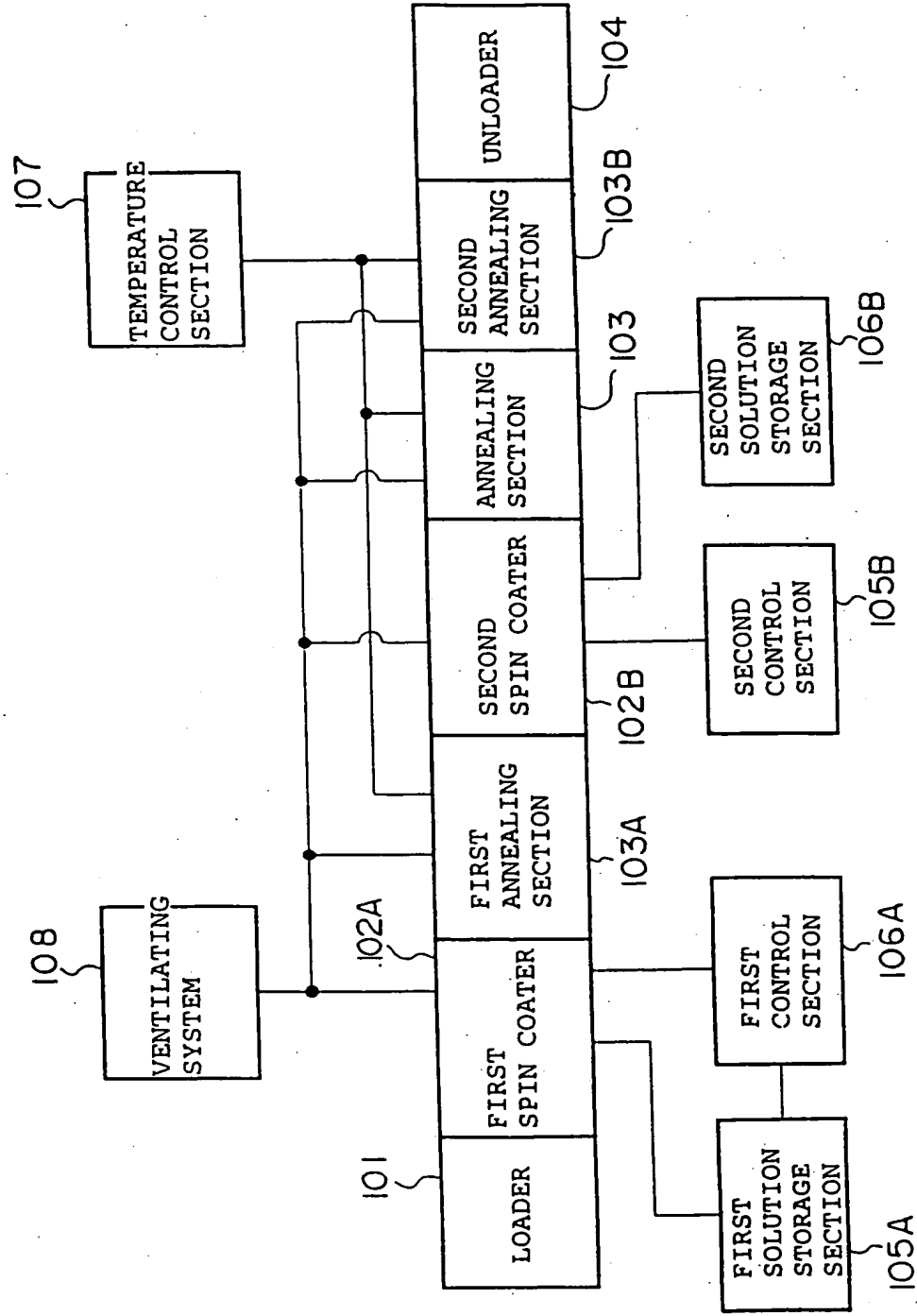


FIG. 7

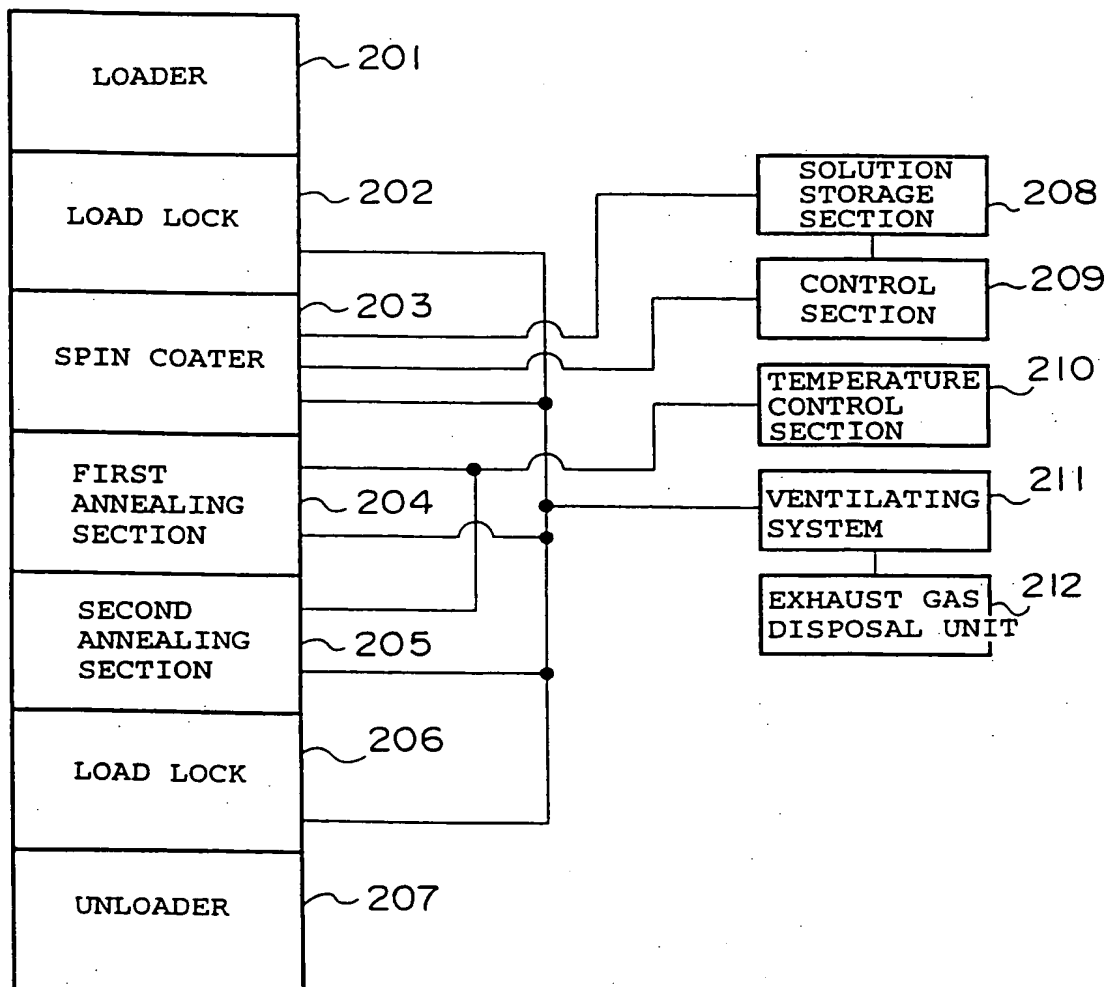


FIG. 8

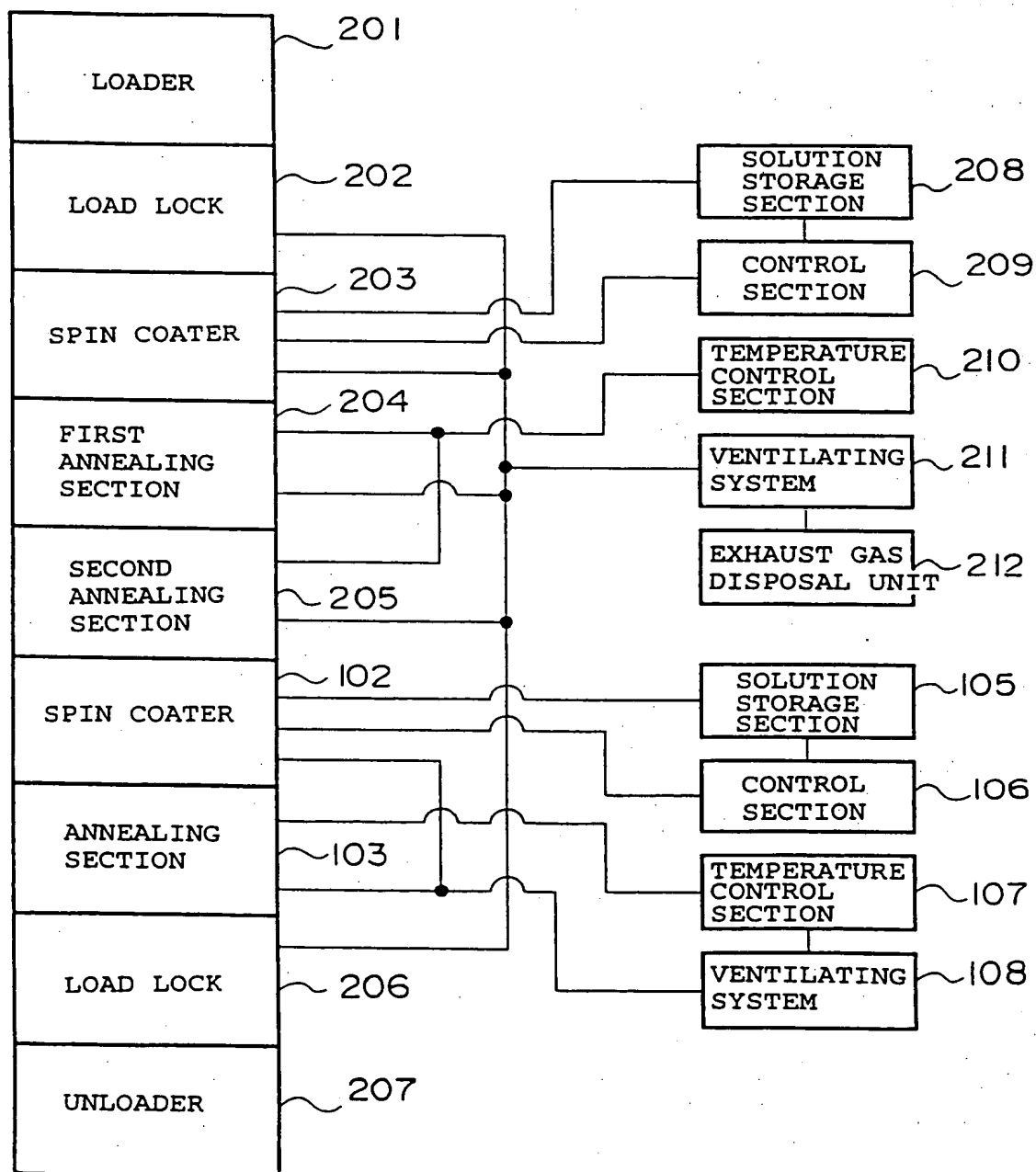


FIG. 9

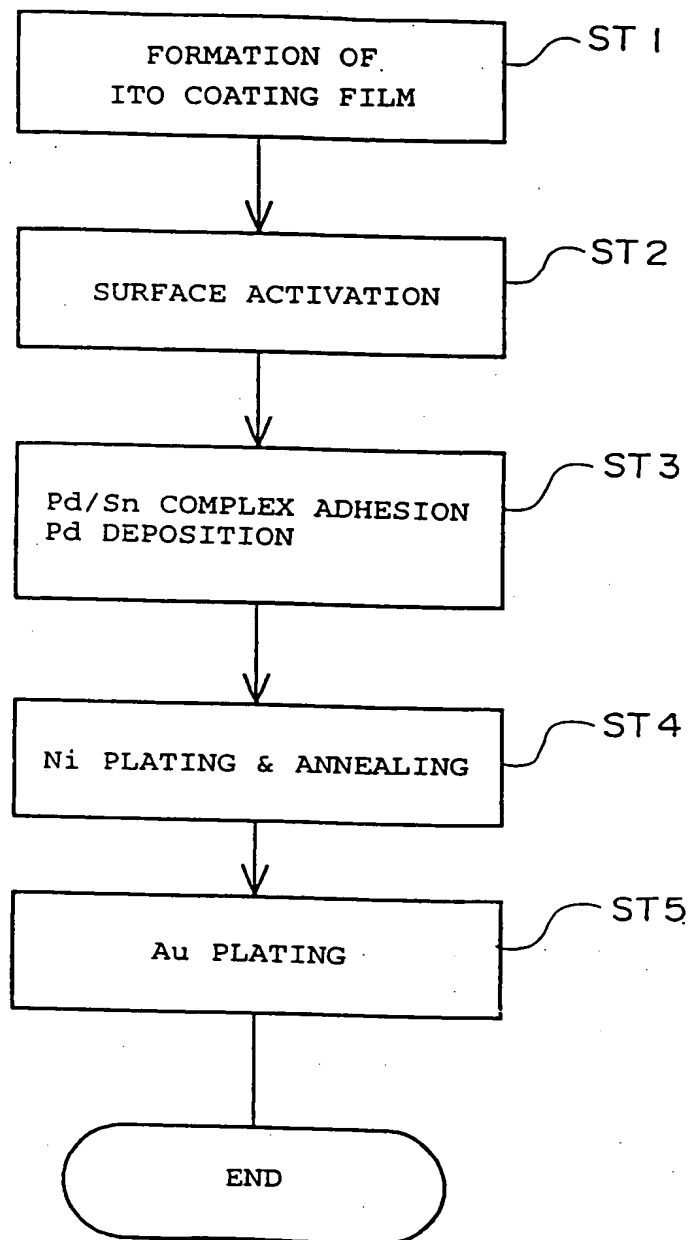




FIG. 10

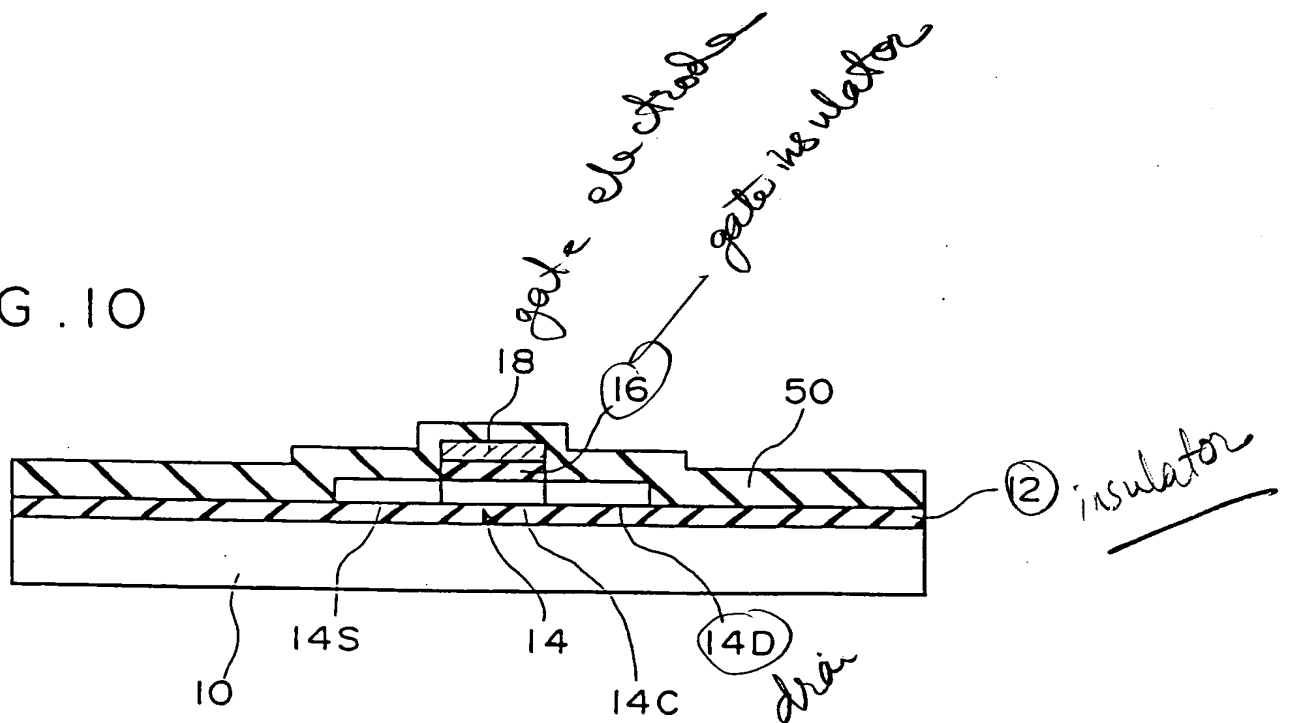


FIG. 11

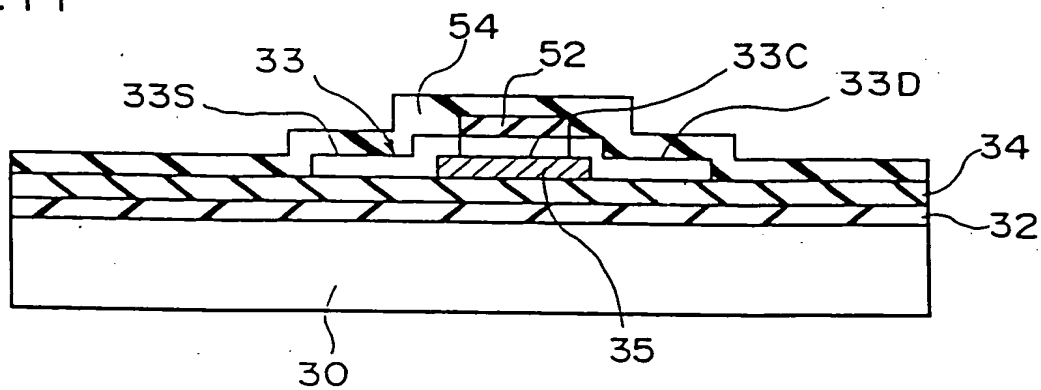


FIG. 12

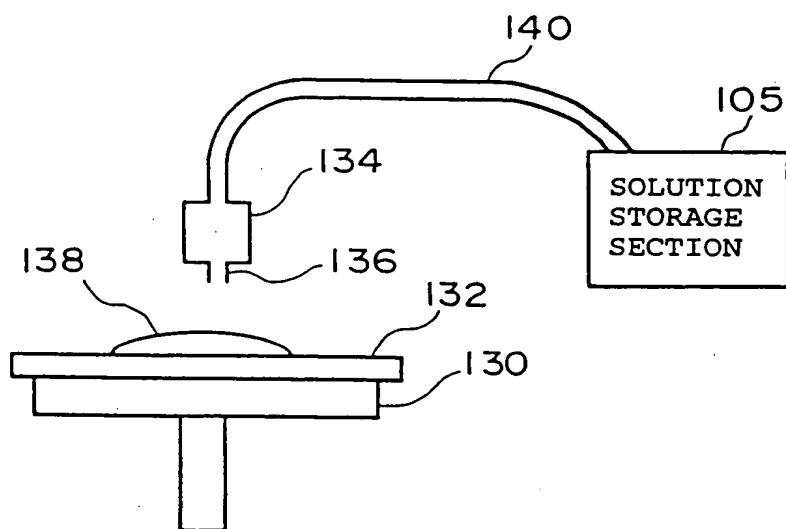


FIG. 13

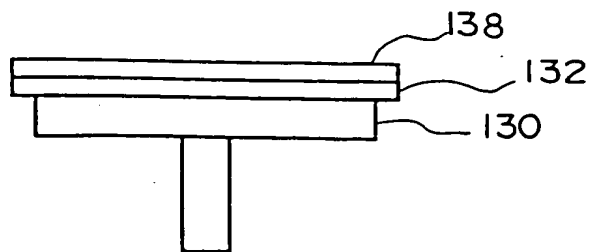


FIG. 14

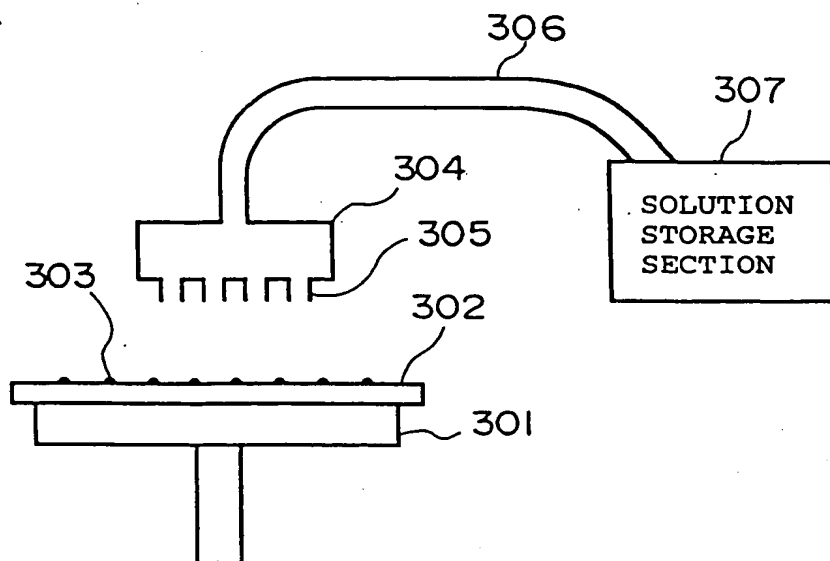


FIG. 15

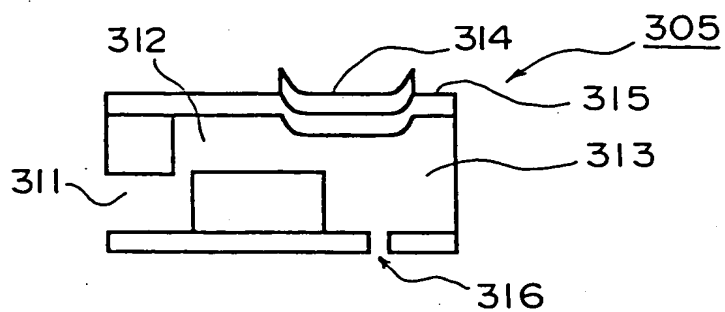


FIG. 16

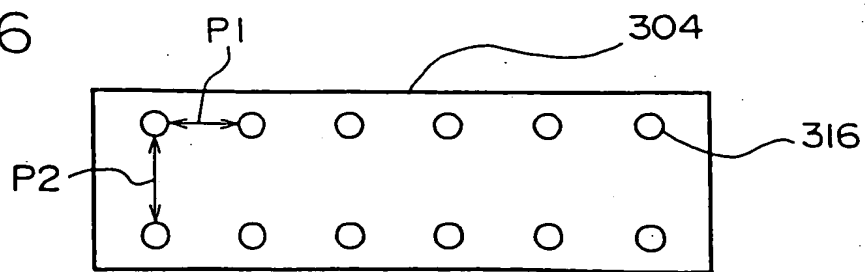


FIG. 17

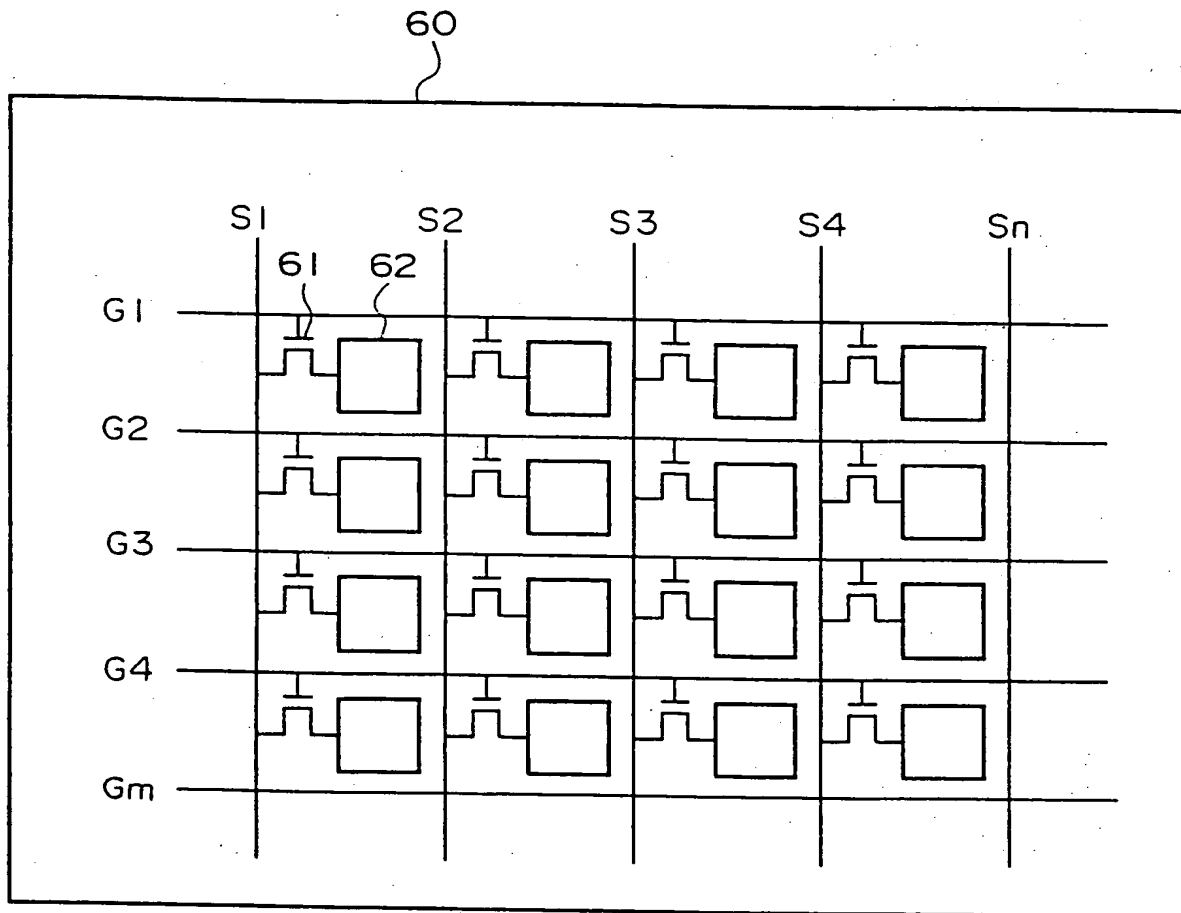


FIG. 18

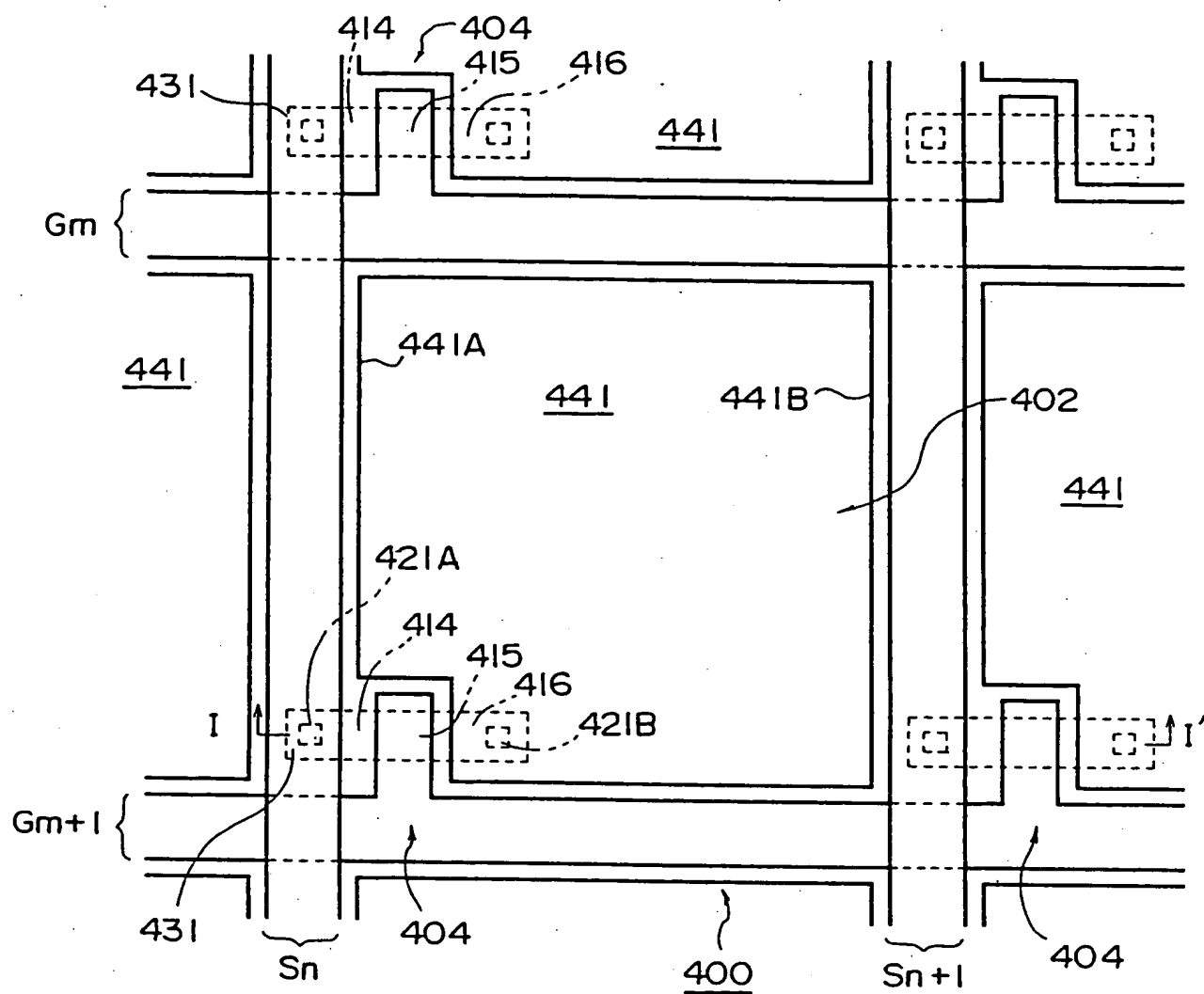
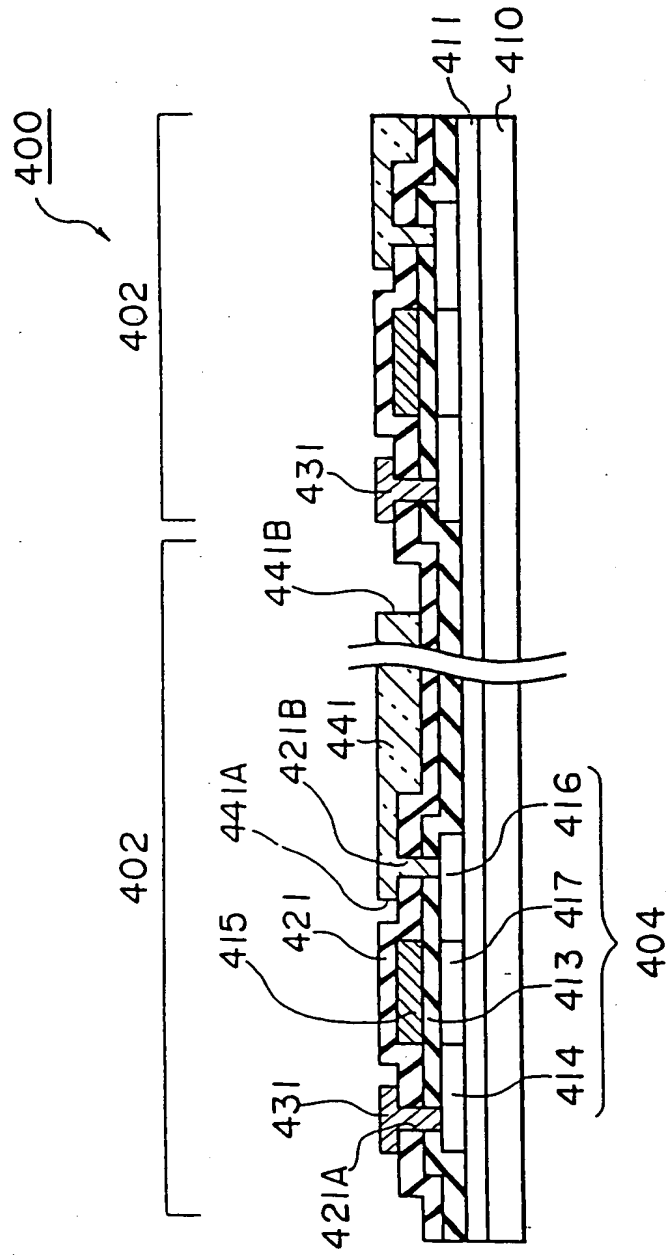


FIG. 19



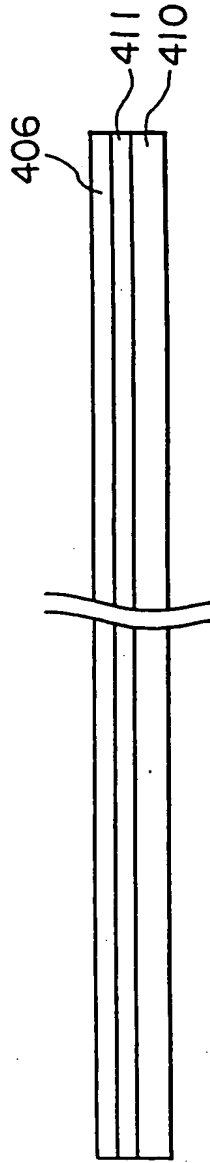


FIG. 20(A)

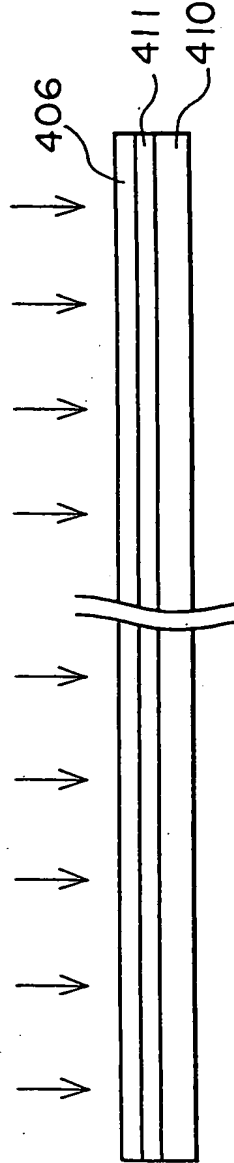


FIG. 20(B)

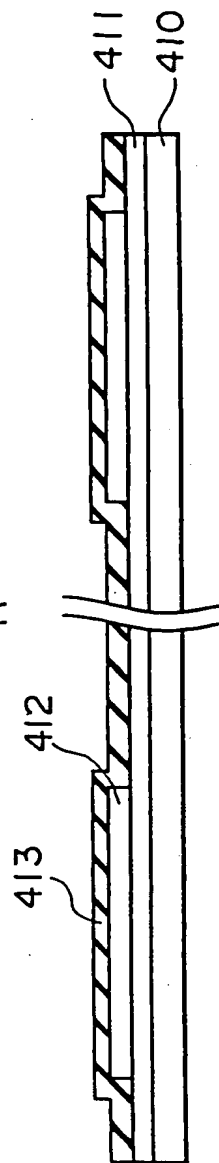


FIG. 20(C)

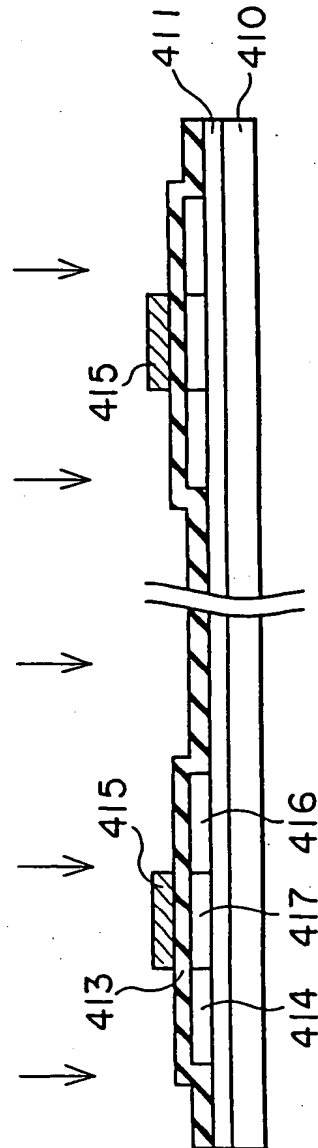


FIG. 20(D)

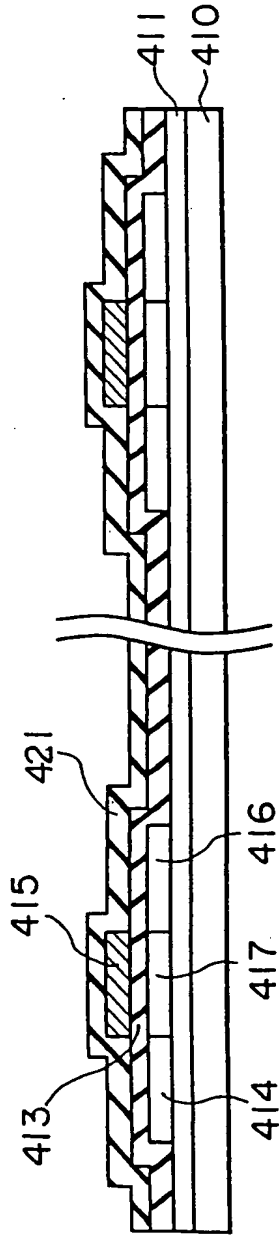


FIG. 2I(A)

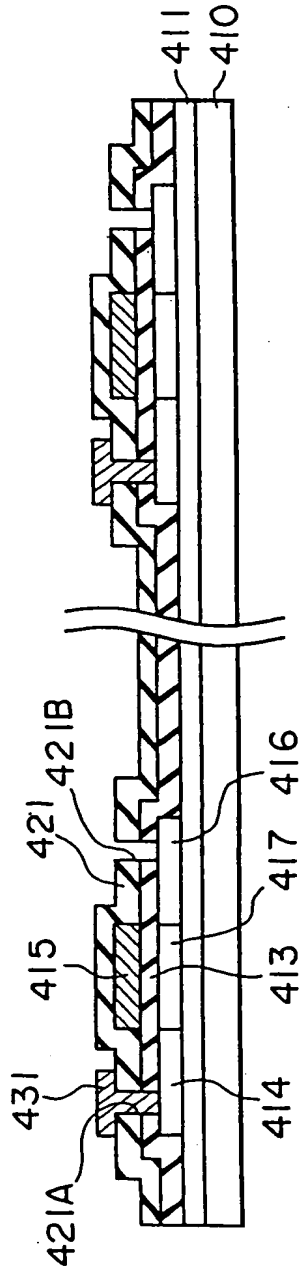


FIG. 2I(B)

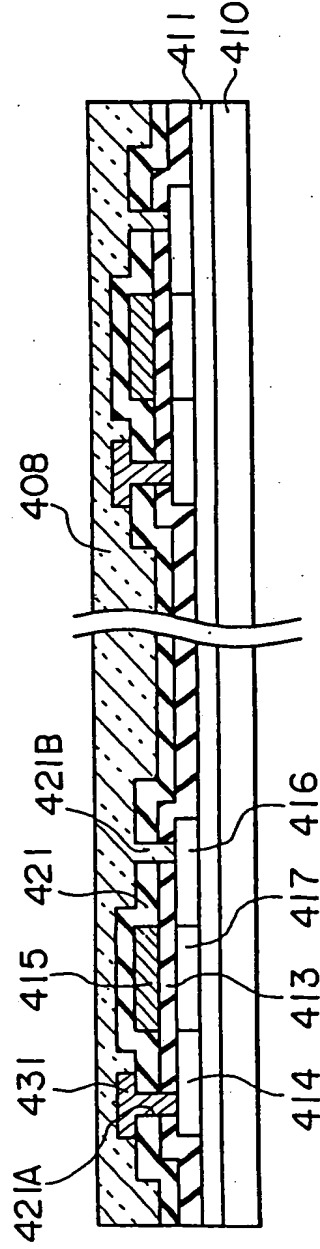


FIG. 2I(C)



FIG. 22

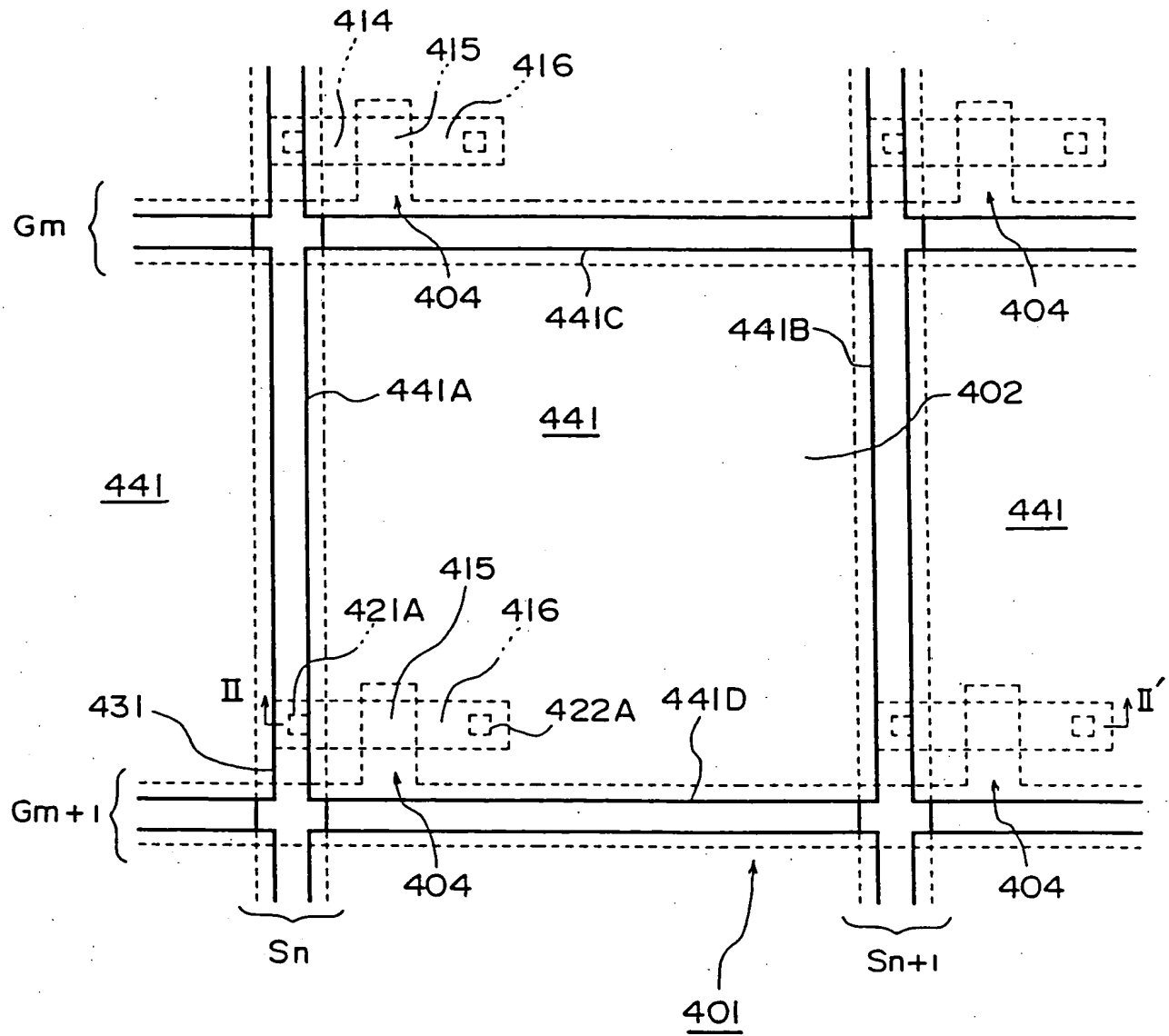




FIG.24(A)

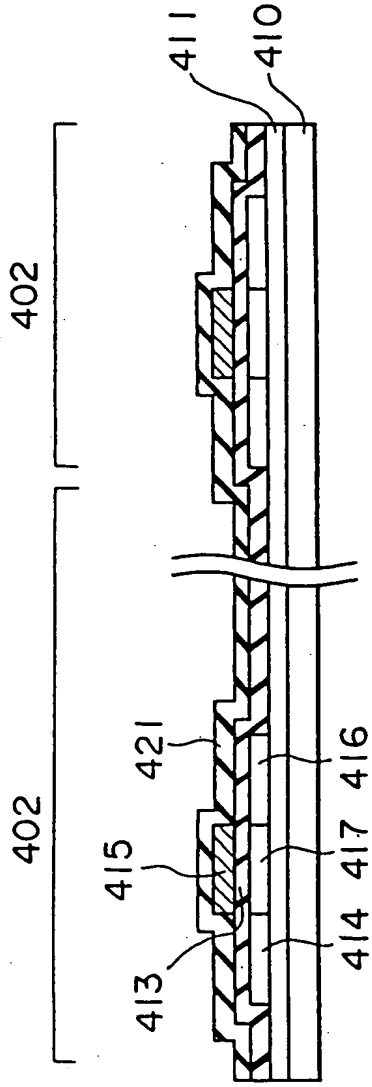


FIG.24(B)

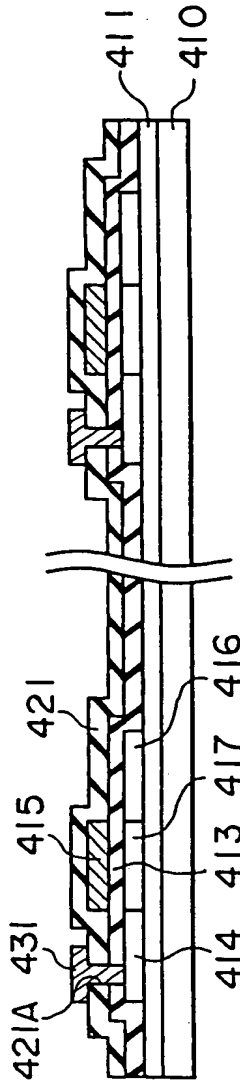


FIG.24(C)

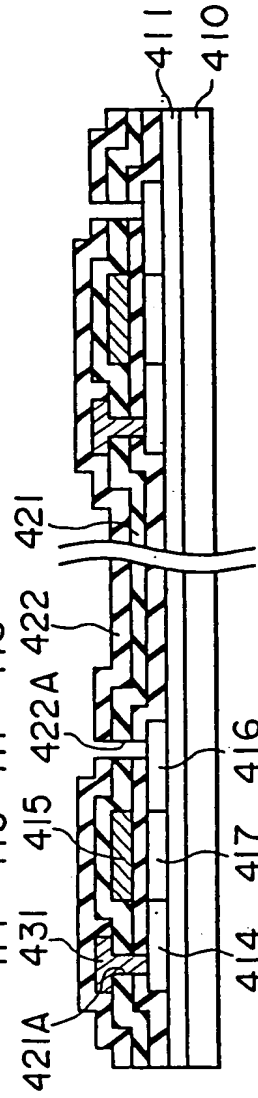


FIG.24(D)

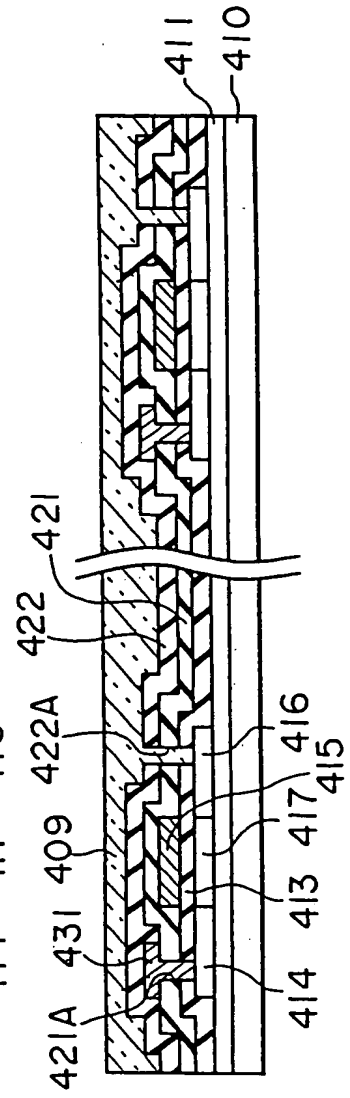


FIG.25(A)

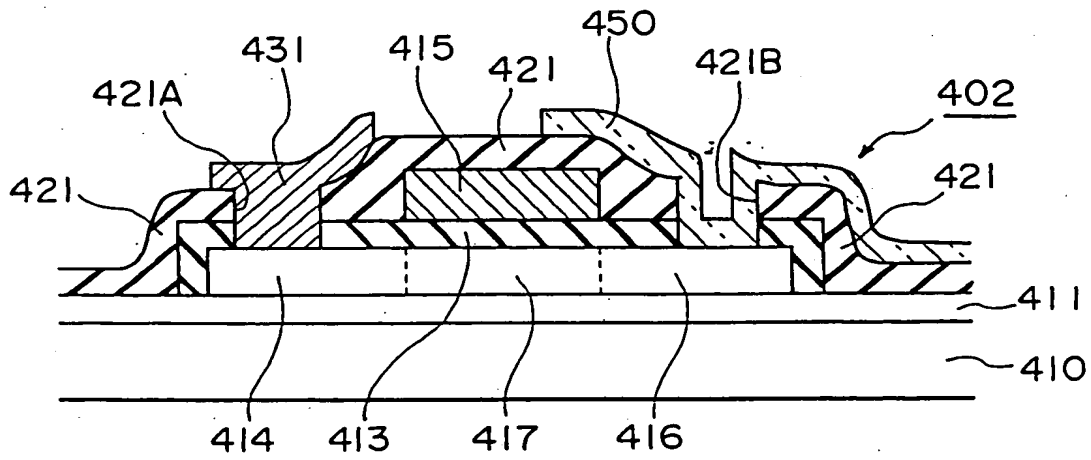


FIG.25(B)

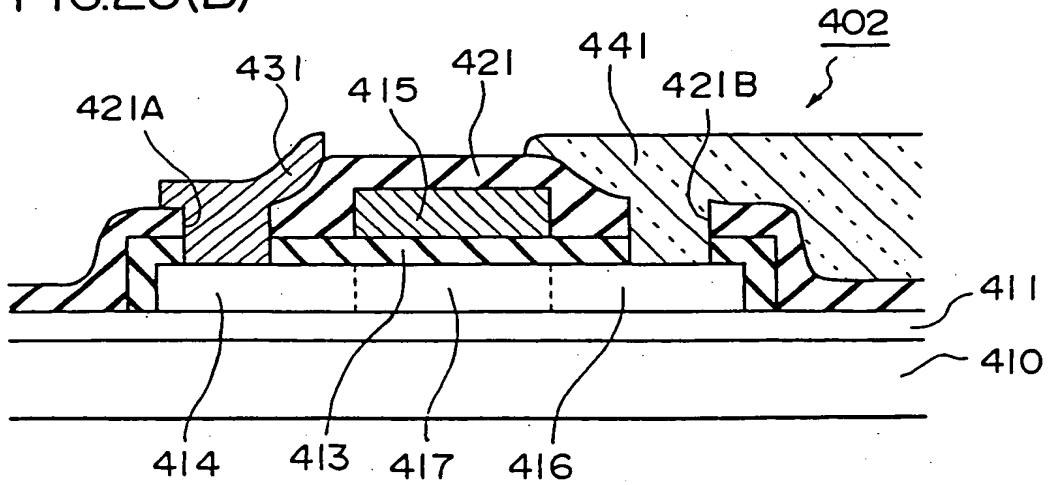


FIG. 26

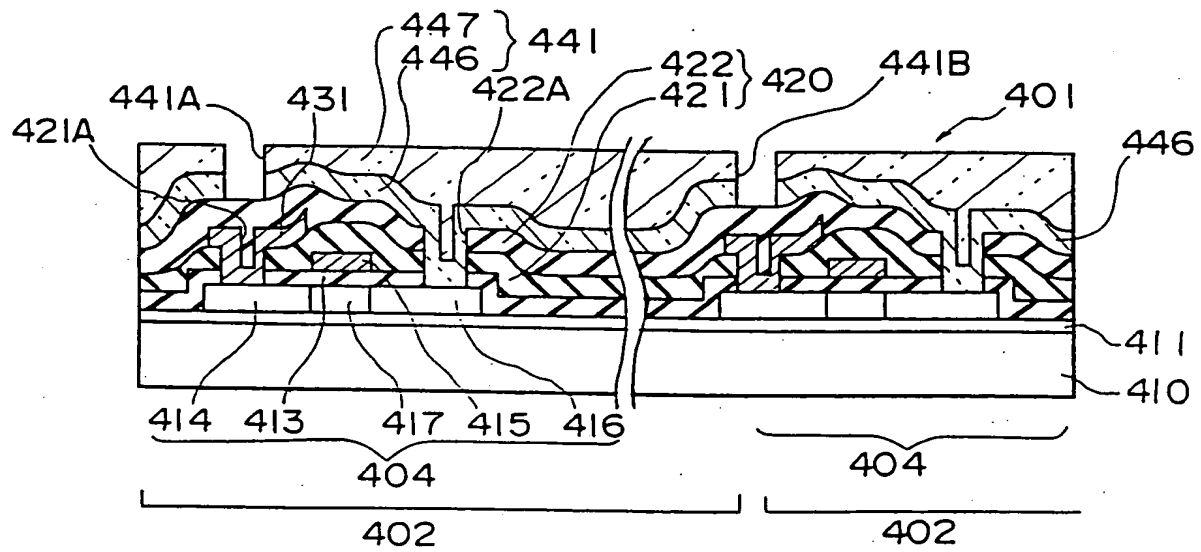


FIG.27(A)

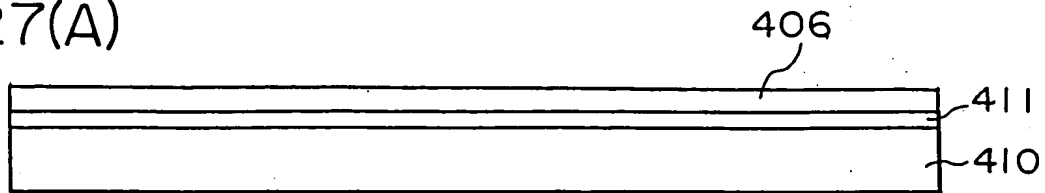


FIG.27(B)

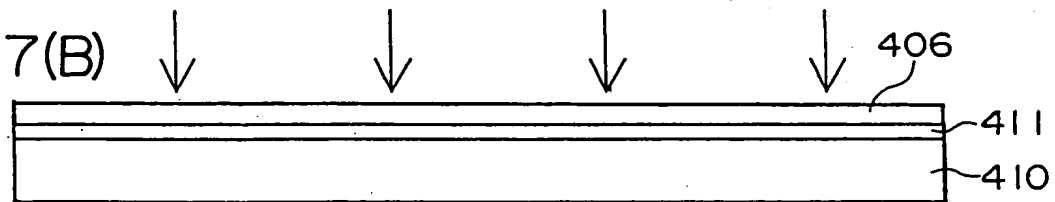


FIG.27(C)

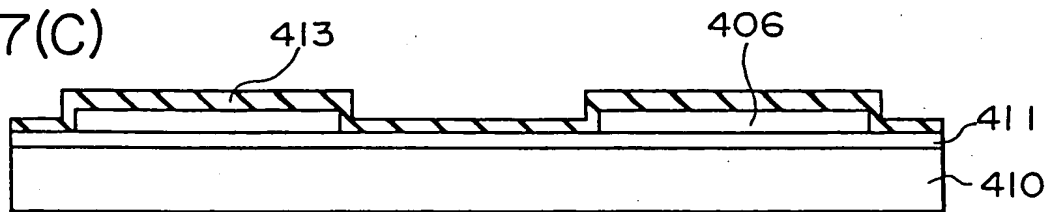


FIG.27(D)

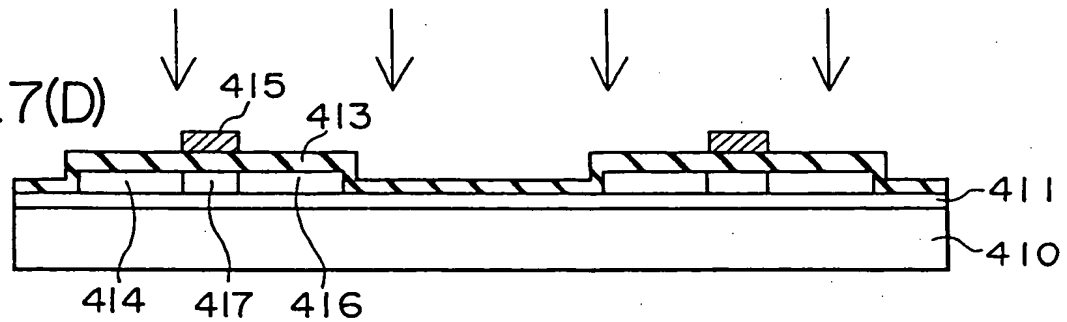
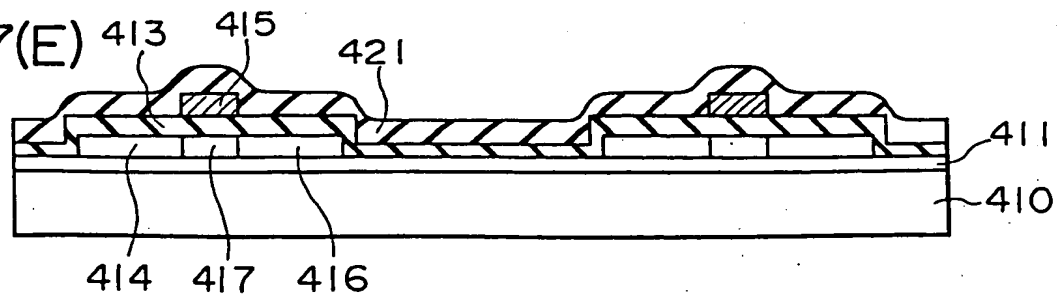


FIG.27(E)



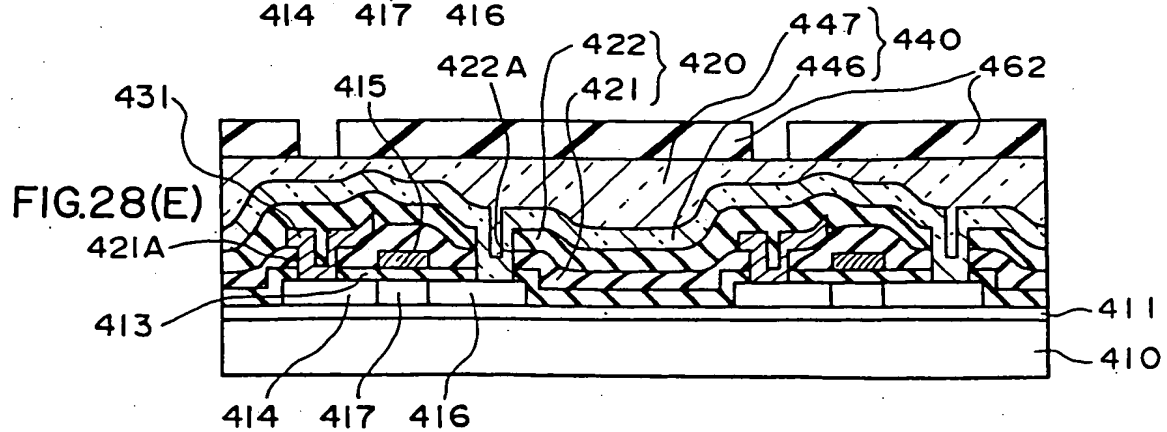
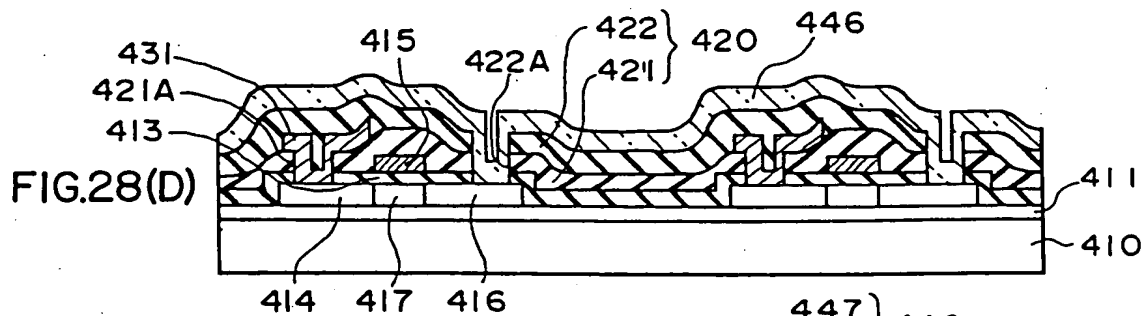
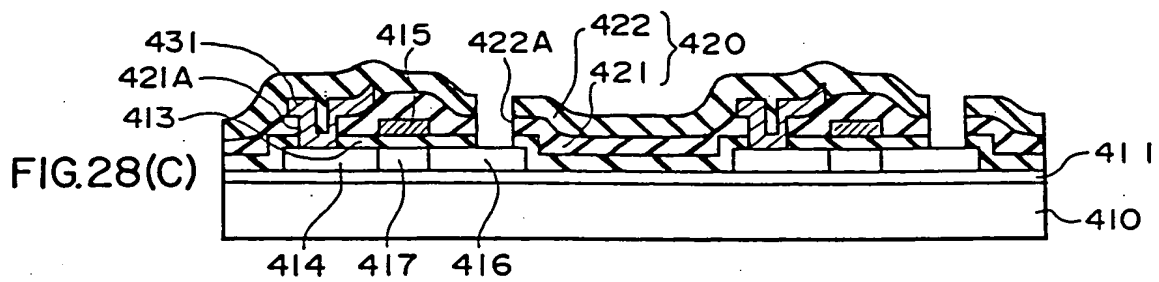
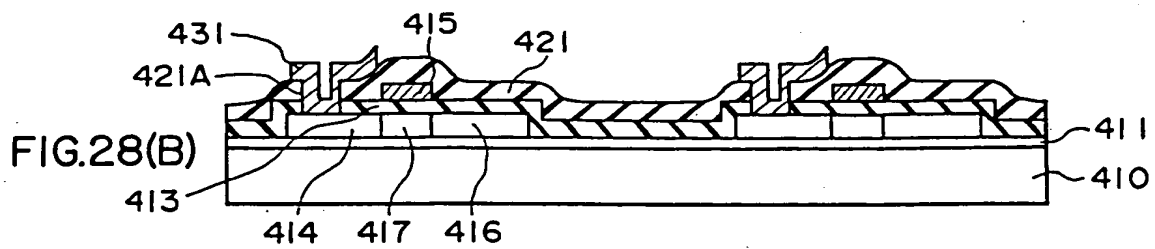
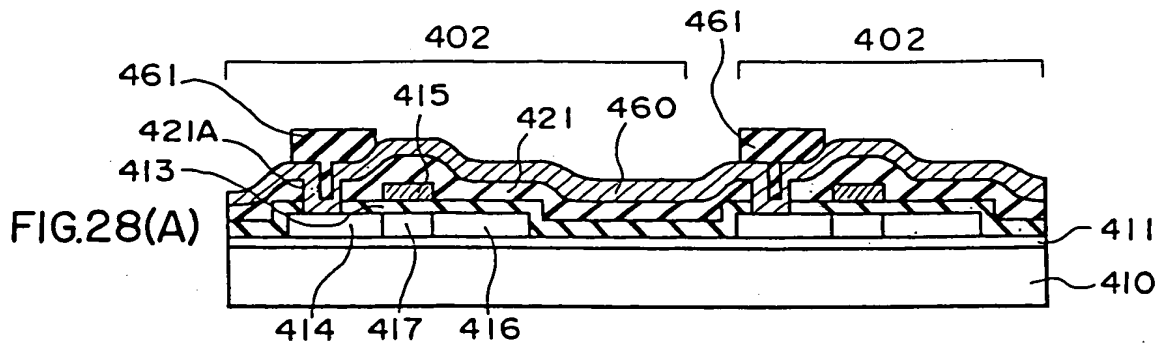


FIG. 29

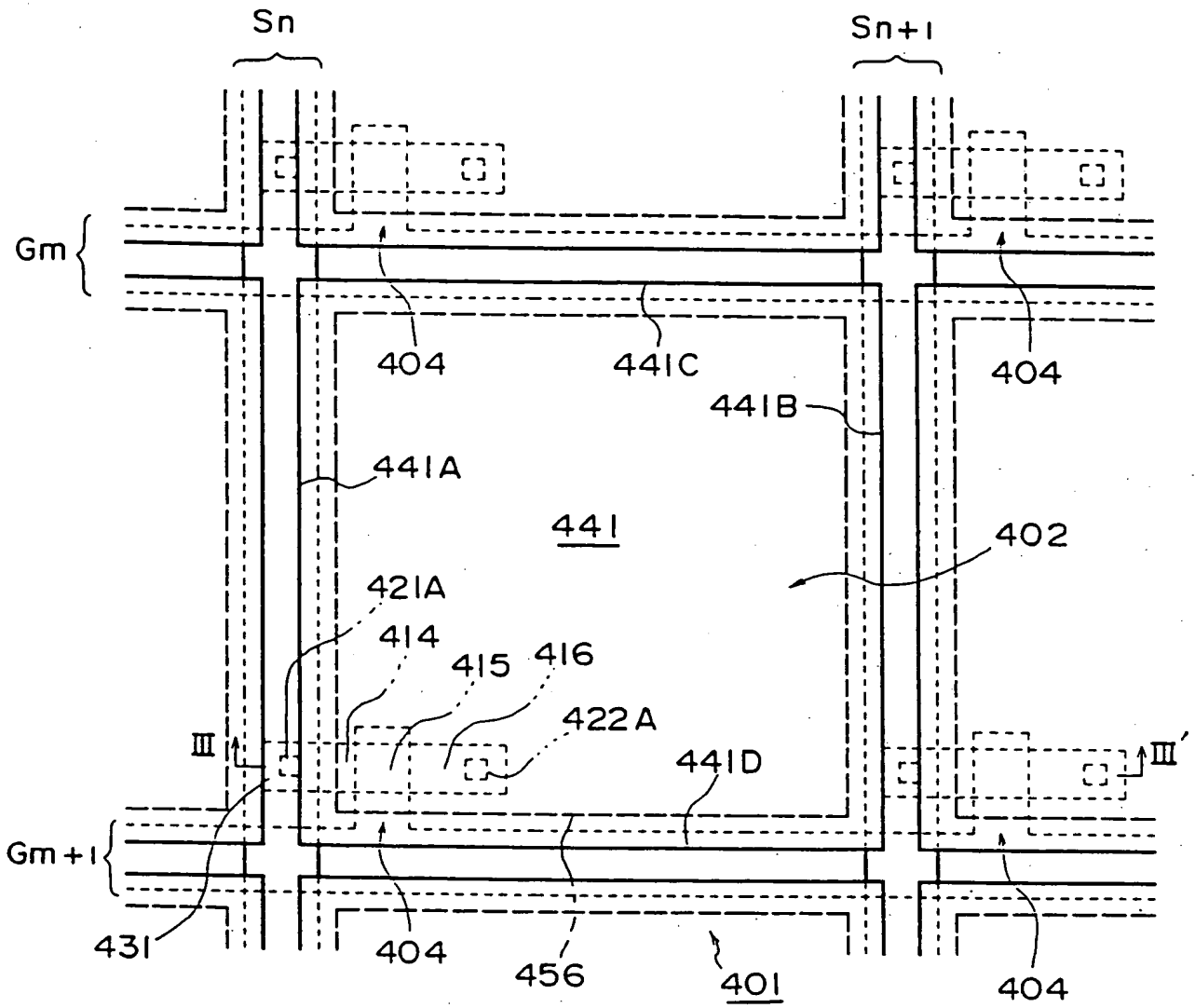
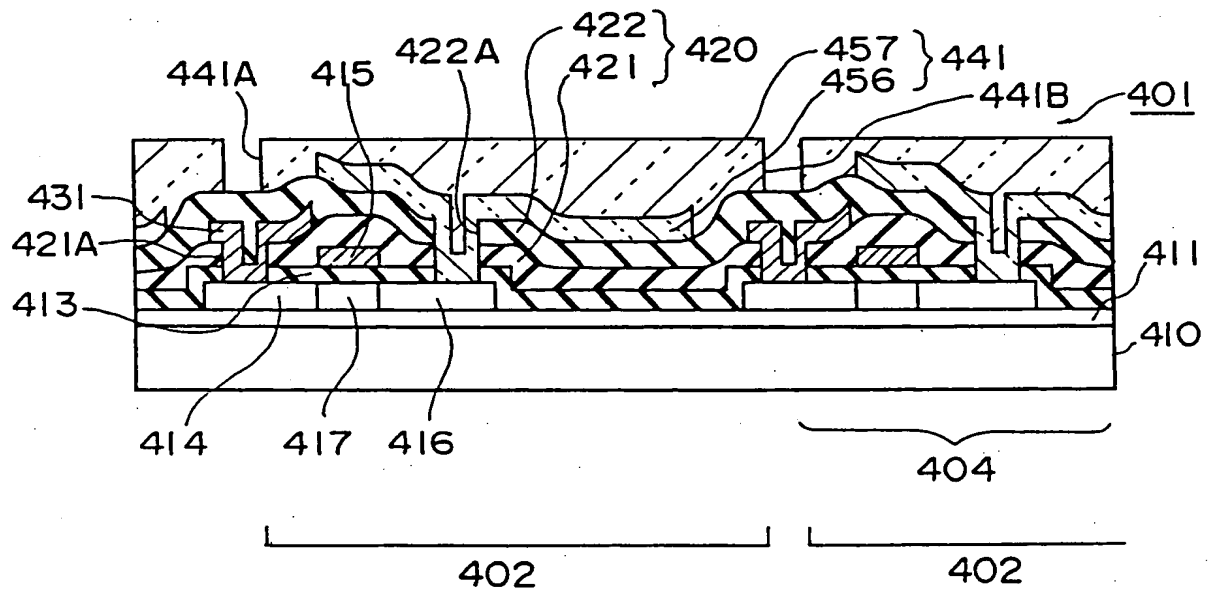




FIG. 30



A cross-sectional view of a semiconductor device. The device consists of a substrate 410 with a base layer 413. Above the base layer is a patterned layer 414. On top of layer 414 is a layer 417, which is further covered by a layer 416. The top surface of layer 416 is patterned into a series of raised regions 402 and recessed regions 401. The raised regions 402 are further divided into sub-regions 421A and 421. A layer 460 is deposited on top of the patterned surface of layer 416. The layer 460 is thicker in the recessed regions 401 and thinner in the raised regions 402. The top surface of layer 460 is labeled 461. The interface between layer 416 and layer 460 is labeled 415.

[illegible]

FIG. 32

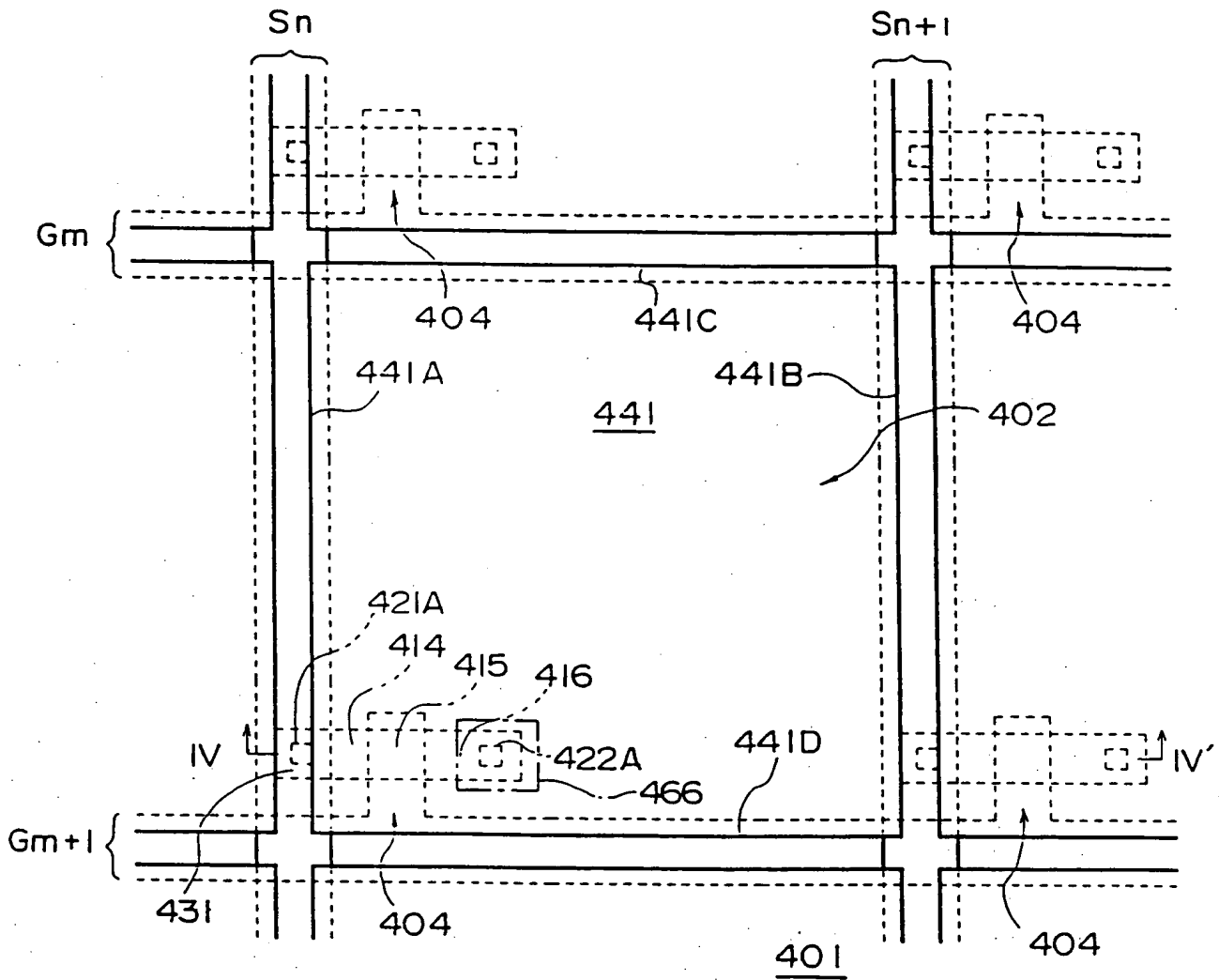


FIG. 33

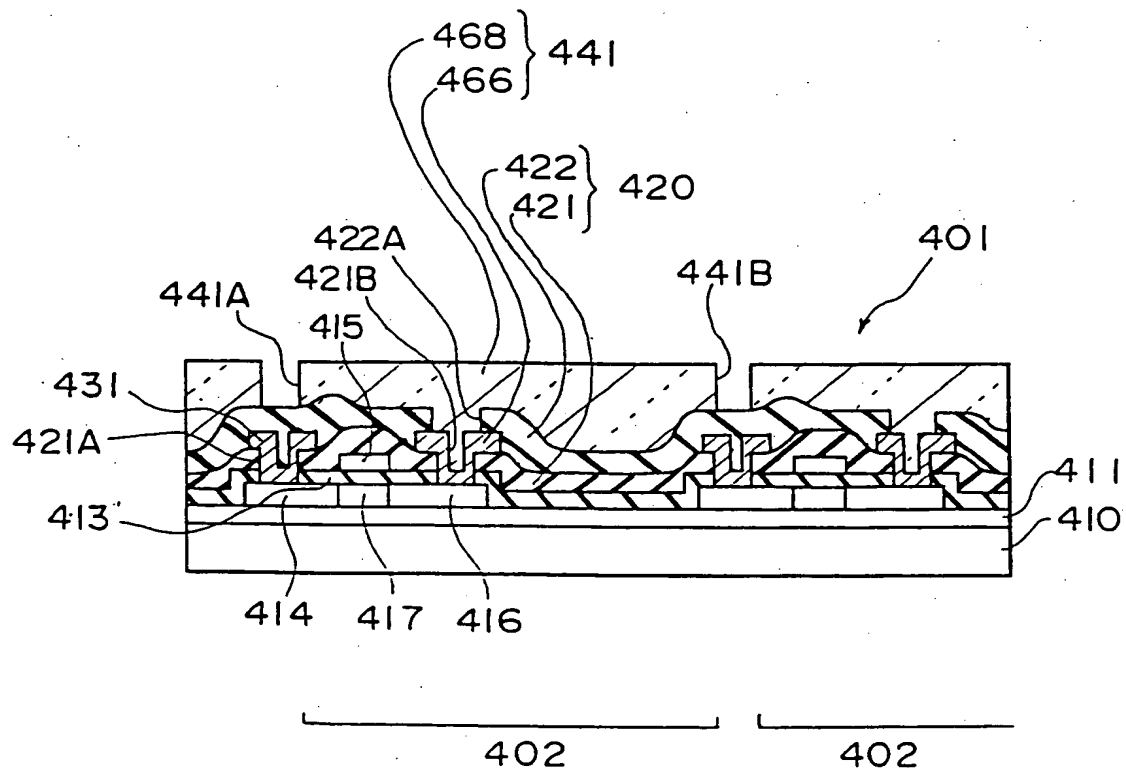


FIG.34(A)

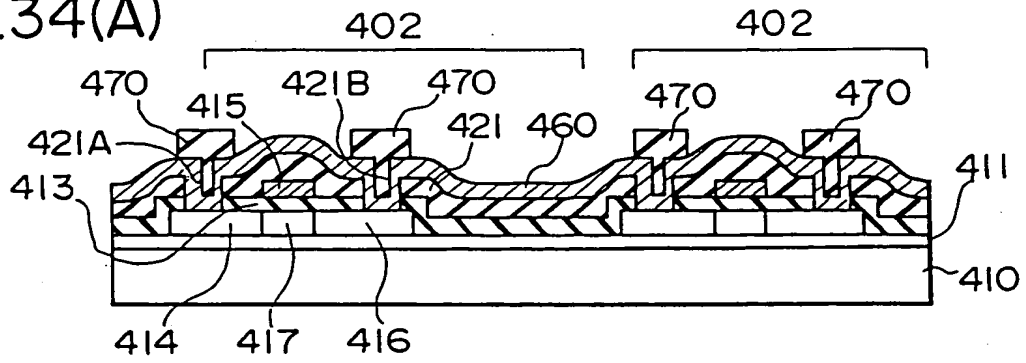


FIG.34(B)

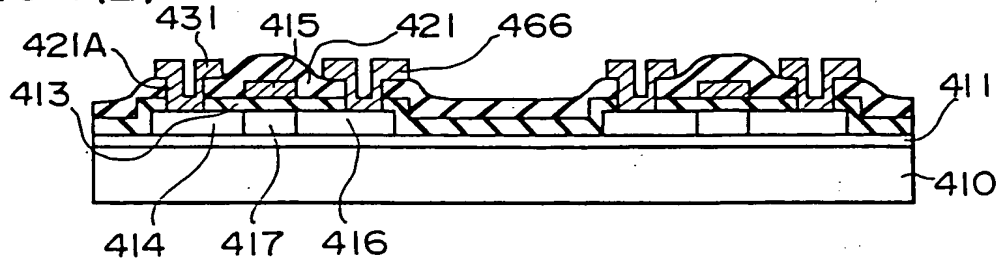


FIG. 34(C)

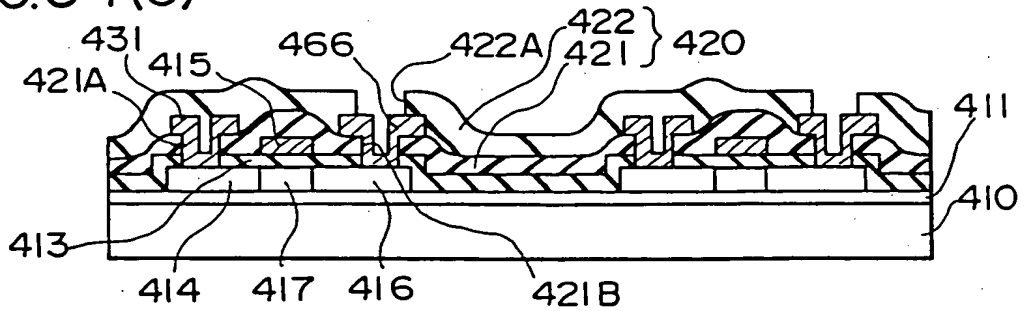


FIG.34(D)

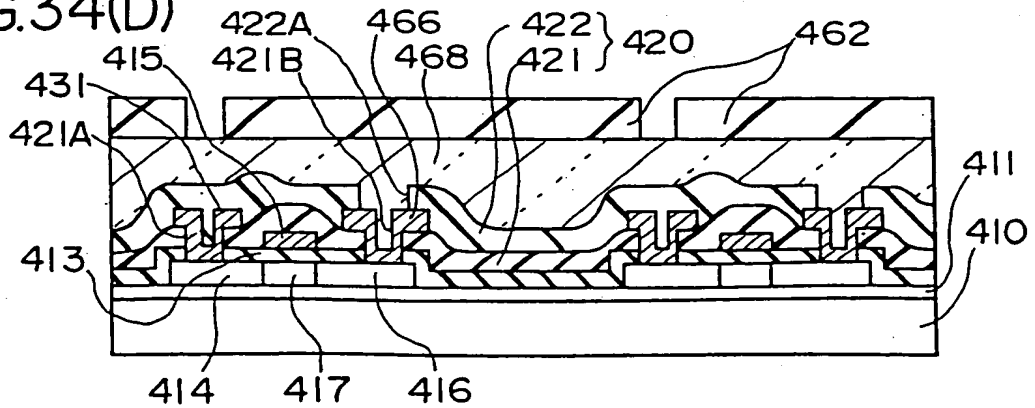


FIG. 35

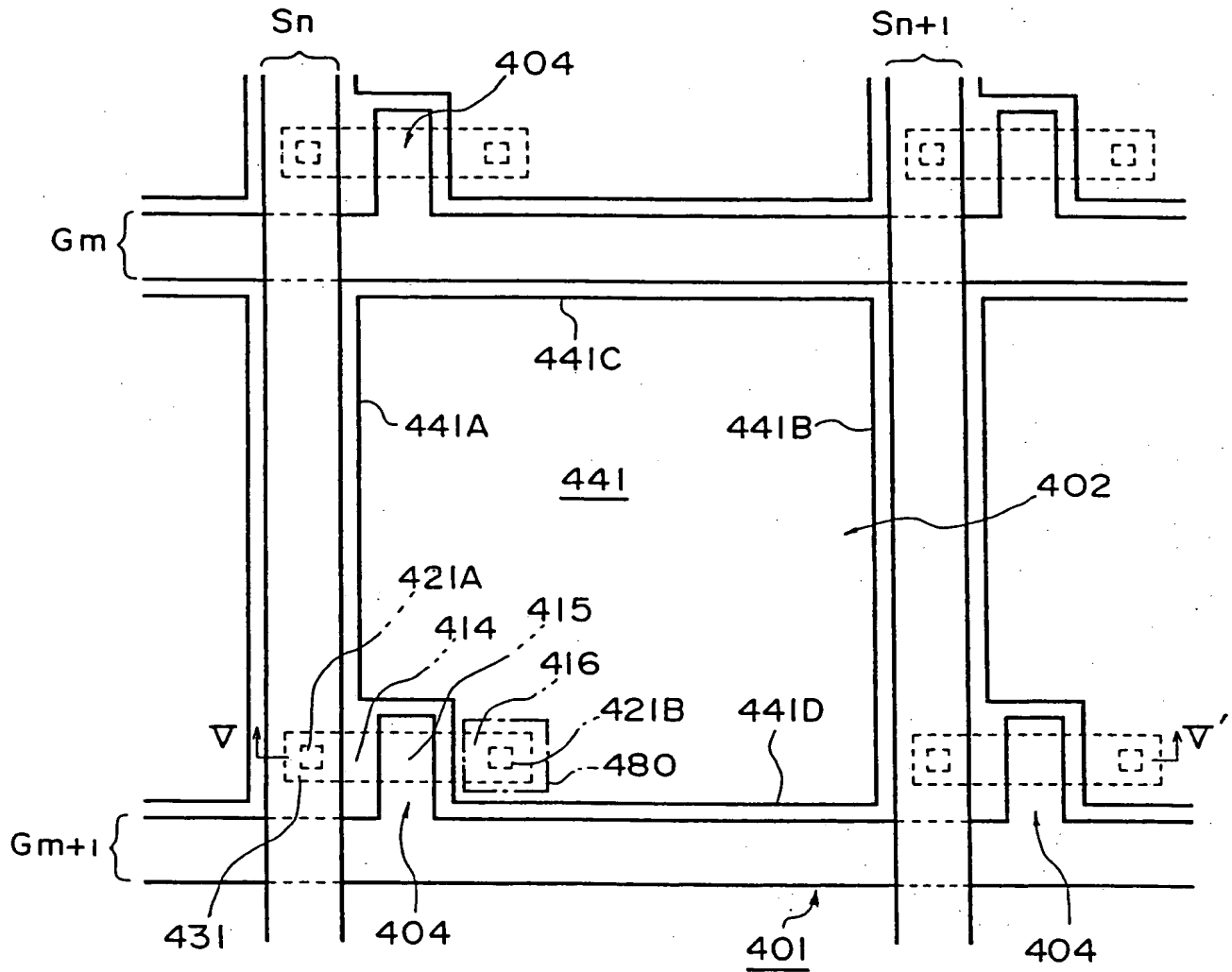


FIG. 36

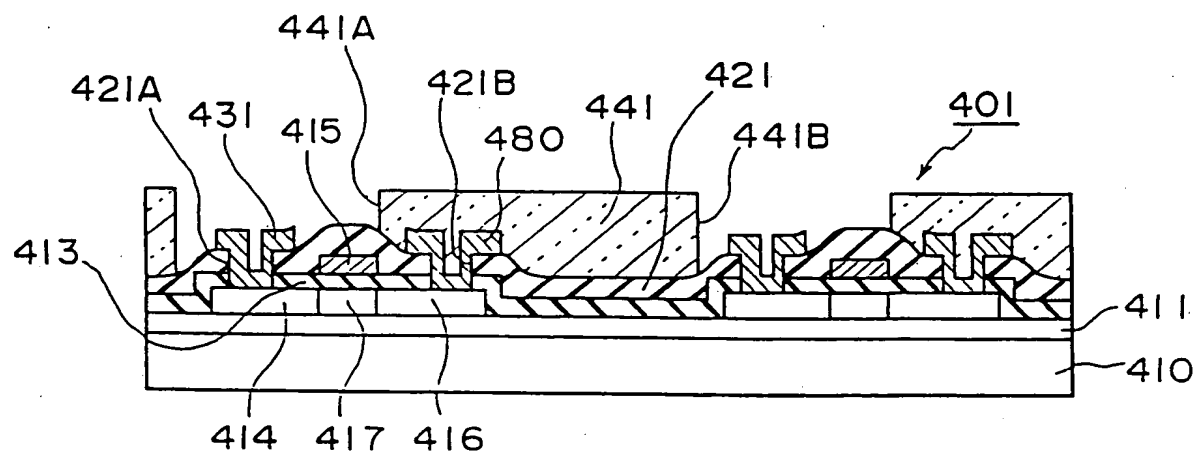


FIG.37(A)

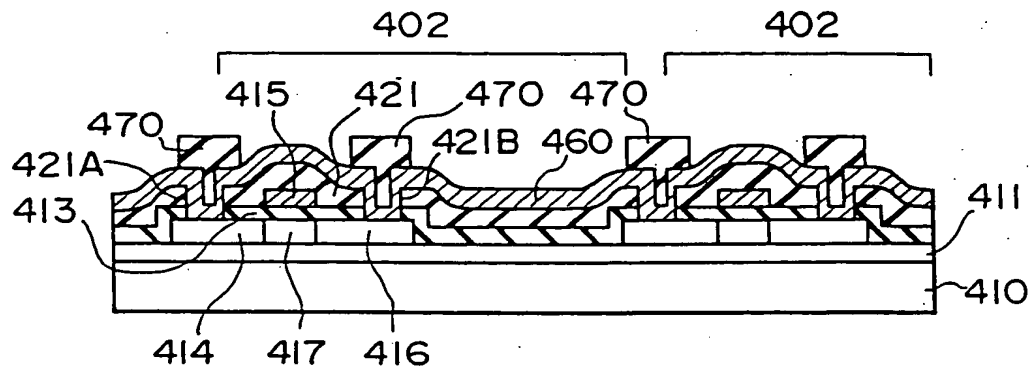


FIG.37(B)

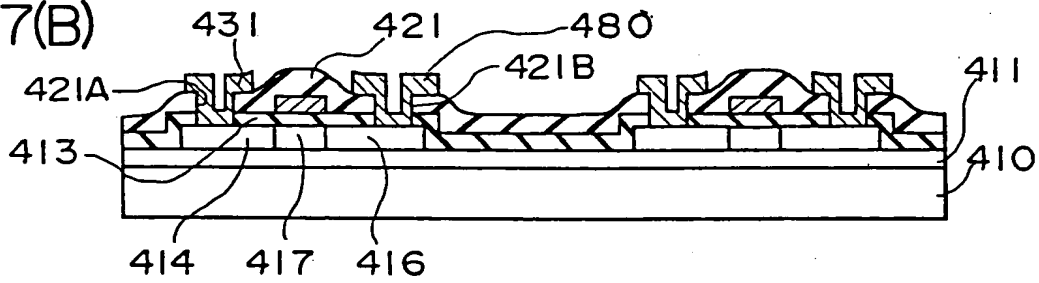


FIG.37(C)

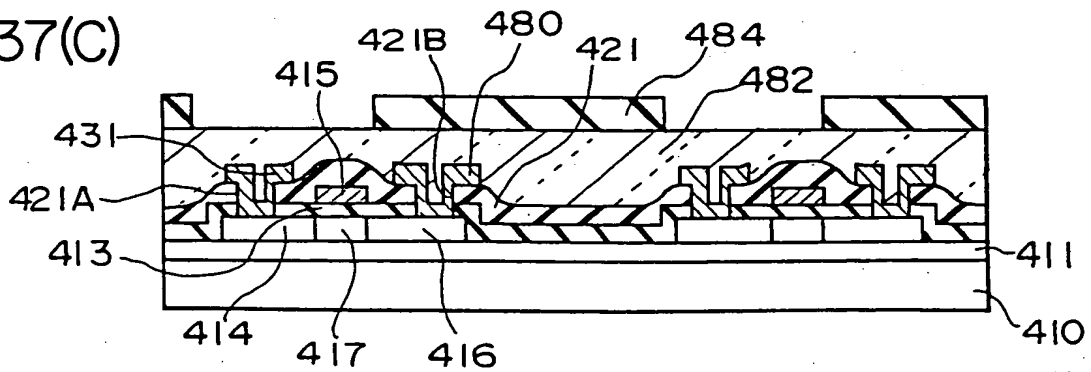




FIG.38(A)

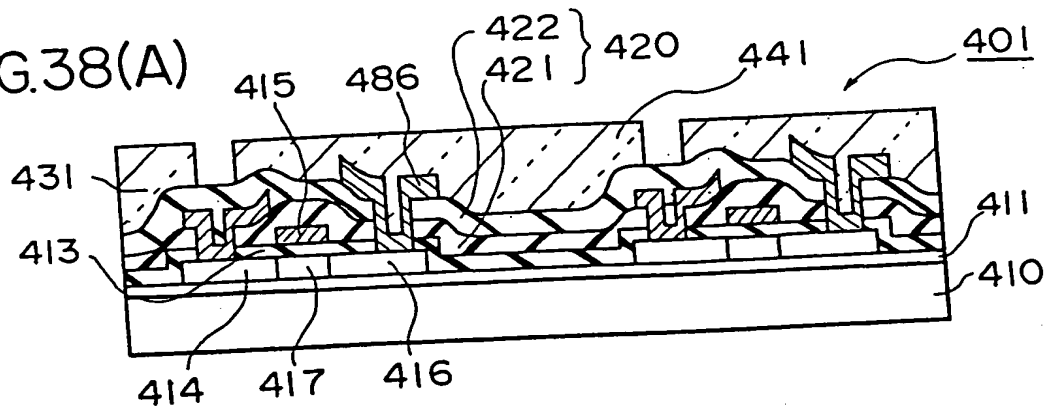


FIG.38(B)

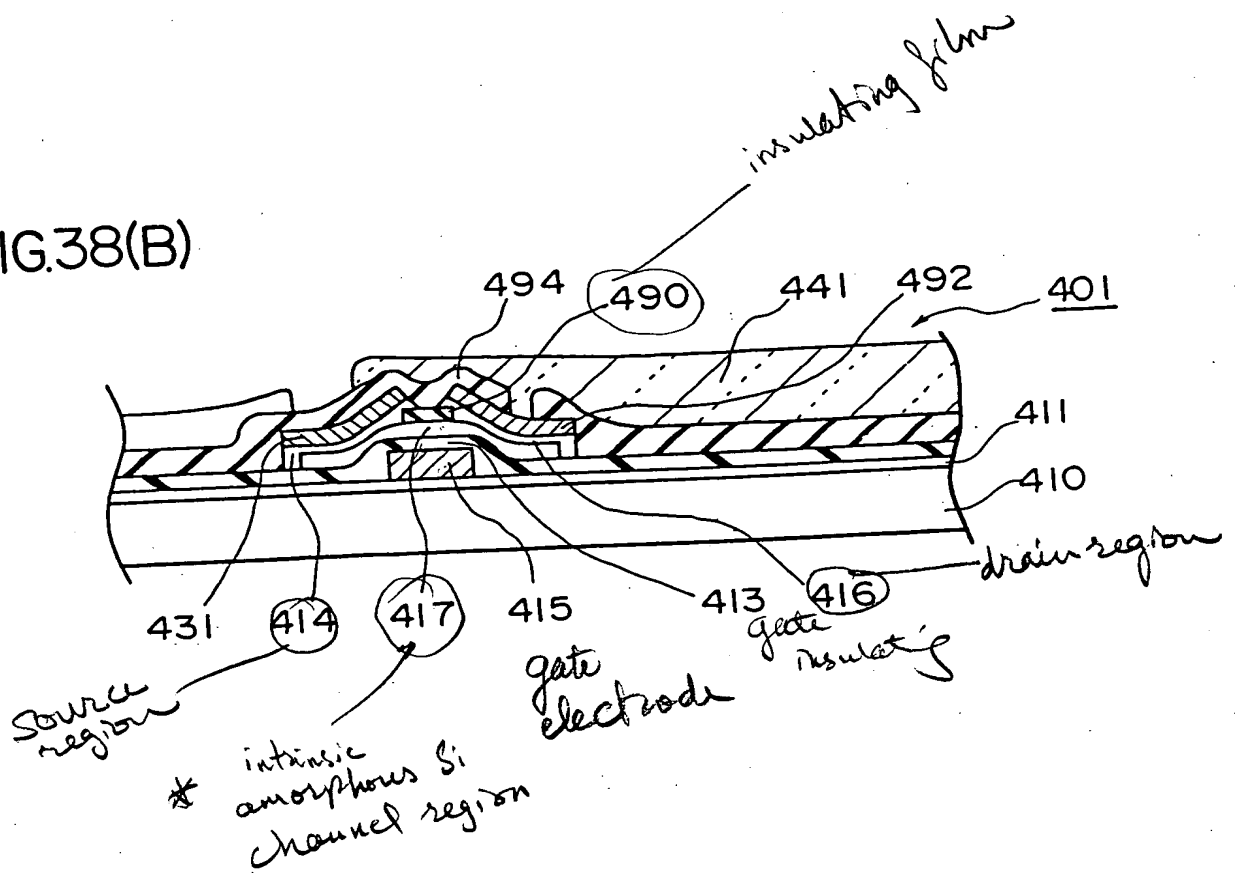


FIG.39(A)

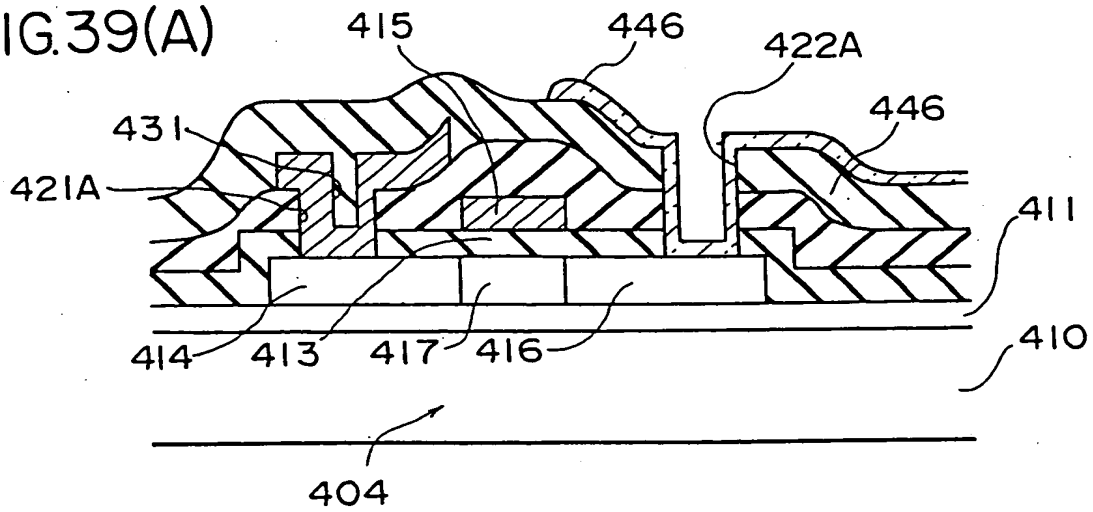


FIG.39(B)

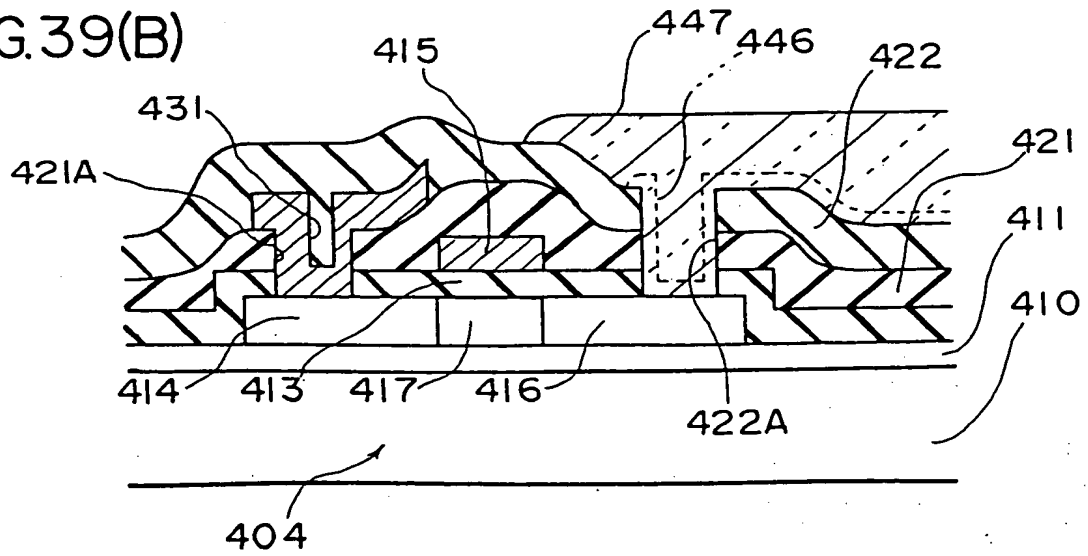


FIG. 40

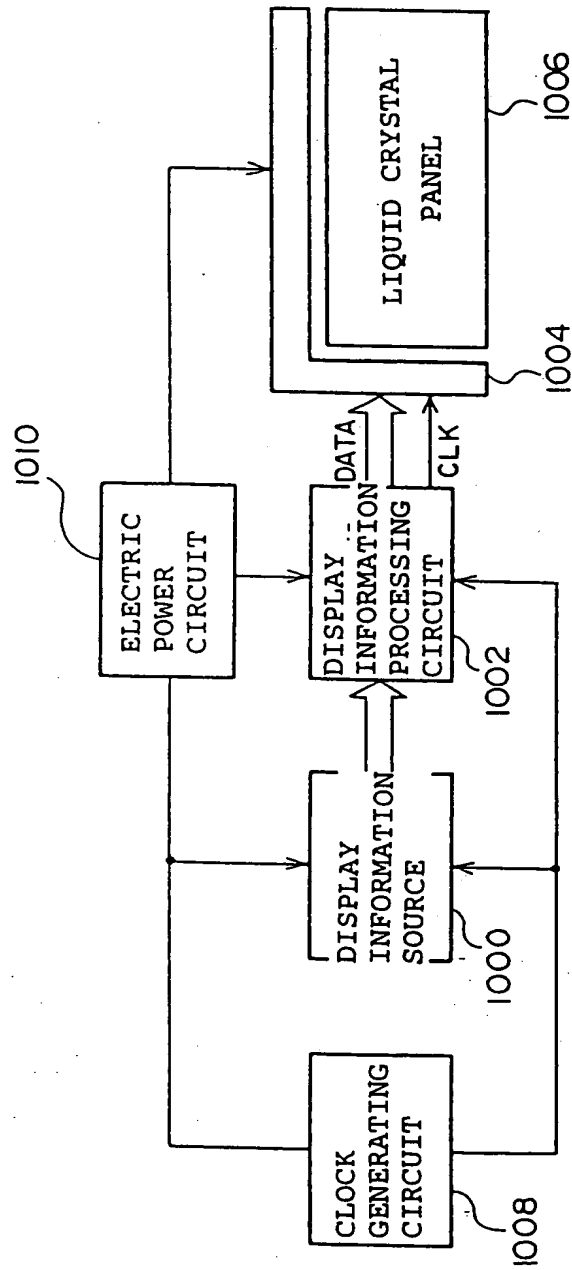




FIG. 42

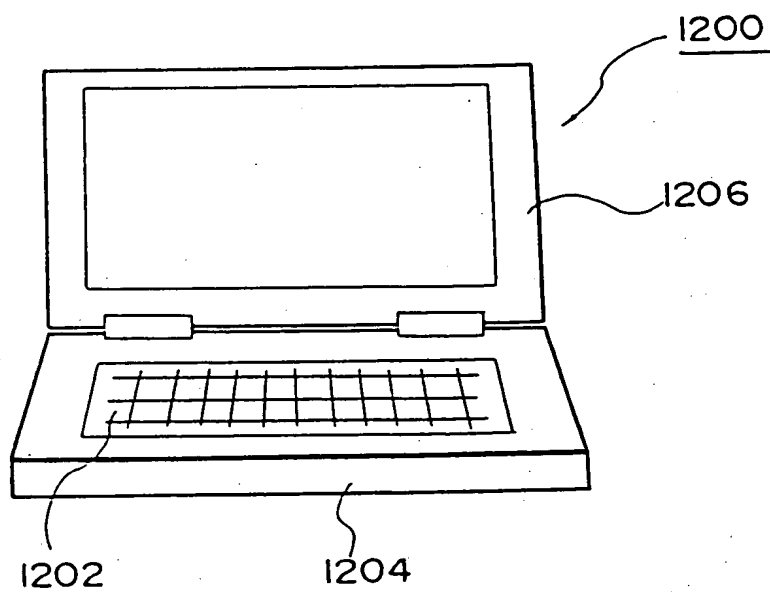


FIG. 43

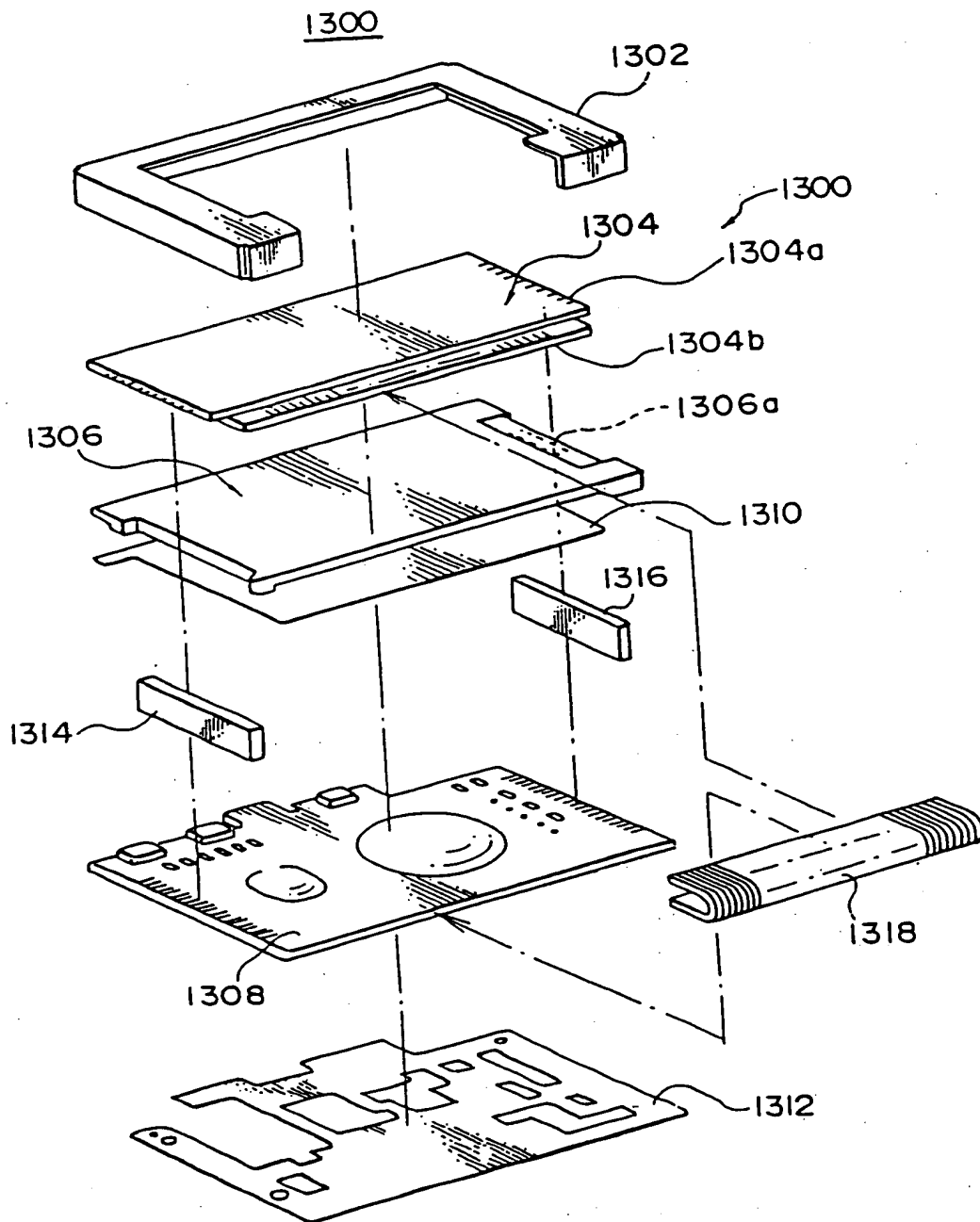


FIG. 44

